SMART ARM-based Microcontroller

SAM L22G / L22J / L22N Summary

DATASHEET SUMMARY

Introduction

Atmel® | SMART SAM L22 is a series of Ultra low-power segment LCD microcontrollers using the 32-bit ARM® Cortex®-M0+ processor, ranging from 48- to 100-pins with up to 256KB Flash and 32KB of SRAM and to drive up to 320 LCD segments. The SAM L22 devices operate at a maximum frequency of 32MHz and reach 2.46 CoreMark®/MHz. With sophisticated power management technologies the SAM L22 devices run down to 39µA/MHz (CPU running CoreMark) in active mode and down to 490nA in ultra low-power backup mode with RTC.

Features

- Processor
  - ARM Cortex-M0+ CPU running at up to 32MHz
    - Single-cycle hardware multiplier
    - Micro Trace Buffer
    - Memory Protection Unit (MPU)
- Memories
  - 64/128/256KB in-system self-programmable Flash
  - 2/4/8KB Flash Read-While-Write section
  - 8/16/32KB SRAM Main Memory
- System
  - Power-on reset (POR) and programmable brown-out detection (BOD)
  - Internal and external clock options
  - External Interrupt Controller (EIC)
    - 16 external interrupts that can use any I/O-Pin
    - One non-maskable interrupt on one I/O-Pin
  - Two-pin Serial Wire Debug (SWD)
- Low Power
  - Idle, Standby, Backup, and Off sleep modes
  - SleepWalking peripherals

- Battery backup support
- Two runtime selectable power/performance levels
- Embedded Buck/LDO regulator supporting on-the-fly selection
- Active mode: <50µA/MHz
- Standby with full retention, RTC and LCD = 3.47µA
  - 2.1µs wake-up time
- Standby with full retention and RTC: 1.87µA
  - 2.1µs wake-up time
- Ultra low power Backup mode with RTC: 490nA
  - 90µs wake-up time

- Peripherals
  - Segment LCD controller
    - Up to 8 (4) common and 40 (44) segment terminals to drive 320 (176) segments
    - Static, ½, 1/3, ¼ bias
    - Internal charge pump able to generate VLCD higher than VDDIO
  - 16-channel Direct Memory Access Controller (DMAC)
  - 8-channel Event System
  - Up to four 16-bit Timer/Counters (TC), each configurable as:
    - 16-bit TC with two compare/capture channels
    - 8-bit TC with two compare/capture channels
    - 32-bit TC with two compare/capture channels, by using two TCs
  - One 24-bit Timer/Counters for Control (TCC), with extended functions:
    - Four compare channels with optional complementary output
    - Generation of synchronized pulse width modulation (PWM) pattern across port pins
    - Deterministic fault protection, fast decay and configurable dead-time between complementary output
    - Dithering that increase resolution with up to 5 bit and reduce quantization error
  - Frequency Meter
  - 32-bit Real Time Counter (RTC) with clock/calendar function
    - 8x32-bit Backup Register
    - Tamper Detection
  - Watchdog Timer (WDT)
  - CRC-32 generator
  - One full-speed (12Mbps) Universal Serial Bus (USB) 2.0 Device
    - Eight endpoints
    - Crystal less operation
  - Up to six Serial Communication Interfaces (SERCOM), each configurable as:
    - USART with full-duplex and single-wire half-duplex configuration
    - ISO7816
    - I^2C up to 3.4MHz[1]
    - SPI
  - One AES encryption engine

[1] Max 1 high-speed mode and max 3 fast mode I^2C

  - One True Random Generator (TRNG)
  - One Configurable Custom Logic (CCL)
  - One 12-bit, 1MSPS Analog-to-Digital Converter (ADC) with up to 20 channels
    - Differential and single-ended input
    - Oversampling and decimation in hardware to support 13-, 14-, 15-, or 16-bit resolution
  - Two Analog Comparators (AC) with window compare function
  - Peripheral Touch Controller (PTC)
    - Up to 256-Channel capacitive touch sensing
      - Maximum Mutual-Cap up to 16x16 channels
      - Maximum Self-Cap up to 24 channels
    - Wake-up on touch in standby mode
- Oscillators
  - 32.768kHz crystal oscillator (XOSC32K)
  - 0.4-32MHz crystal oscillator (XOSC)
  - 32.768kHz ultra-low-power internal oscillator (OSCULP32K)
  - 16/12/8/4MHz high-accuracy internal oscillator (OSC16M)
  - 48MHz Digital Frequency Locked Loop (DFLL48M)
  - 96MHz Fractional Digital Phased Locked Loop (FDPLL96M)
- I/O
  - Up to 82 programmable I/O pins
  - Up to 52 segment LCD pins can be used as GPIO/GPI
  - Up to 5 wake-up pins with optional debouncing
  - Up to 5 tamper input pins
  - 1 tamper output pin
- Pin and code compatible with SAM D and SAM L Cortex-M0+ Families[2]
- Packages
  - 100-pin TQFP
  - 64-pin TQFP, QFN
  - 49-pin WLCSP
  - 48-pin TQFP, QFN
- Operating Voltage
  - 1.62V – 3.63V

[2] except the VLCD

Table of Contents

1. Description

Atmel | SMART SAM L22 is a series of Ultra low-power segment LCD microcontrollers using the 32-bit ARM® Cortex®-M0+ processor, ranging from 48- to 100-pins with up to 256KB Flash and 32KB of SRAM and can drive up to 320 LCD segments. The SAM L22 devices operate at a maximum frequency of 32MHz and reach 2.46 Coremark/MHz. They are designed for simple and intuitive migration with identical peripheral modules, hex compatible code, identical linear address map and pin compatible migration paths between all devices in the product series. All devices include intelligent and flexible peripherals, Atmel Event System for inter-peripheral signaling, and support for capacitive touch button, slider and wheel user interfaces.

The Atmel SAM L22 devices provide the following features: Segment LCD (SLCD) controller with up to 48 selectable SLCD pins from max. 52 pins to drive up to 320 segments, all SLCD Pins can be used also as GPIOs (100-pin package: 8 of the SLCD pins can be used only as GP input), in-system programmable Flash, sixteen-channel direct memory access (DMA) controller, 8 channel Event System, programmable interrupt controller, up to 82 programmable I/O pins, 32-bit real-time clock and calendar, up to four 16-bit Timer/Counters (TC) and one 24-bit Timer/Counters for Control (TCC), where each TC can be configured to perform frequency and waveform generation, accurate program execution timing or input capture with time and frequency measurement of digital signals. The TCs can operate in 8- or 16-bit mode, selected TCs can be cascaded to form a 32-bit TC, and the TCC has extended functions optimized for motor, lighting and other control applications. The series provide one full-speed USB 2.0 device interface; up to six Serial Communication Modules (SERCOM) that each can be configured to act as an USART, UART, SPI, I^2C up to 3.4MHz, SMBus, PMBus, and ISO7816 smart card interface; up to twenty channel 1Msps 12-bit ADC with optional oversampling and decimation supporting up to 16-bit resolution, two analog comparators with window mode, Peripheral Touch Controller supporting up to 256 buttons, sliders, wheels and proximity sensing; programmable Watchdog Timer, brown-out detector and power-on reset and two-pin Serial Wire Debug (SWD) program and debug interface.

All devices have accurate and low-power external and internal oscillators. All oscillators can be used as a source for the system clock. Different clock domains can be independently configured to run at different frequencies, enabling power saving by running each peripheral at its optimal clock frequency, and thus maintaining a high CPU frequency while reducing power consumption.

The SAM L22 devices have four software-selectable sleep modes, idle, standby, backup and off. In idle mode the CPU is stopped while all other functions can be kept running. In standby all clocks and functions are stopped expect those selected to continue running. In this mode all RAMs and logic contents are retained. The device supports SleepWalking. This feature allows the peripheral to wake up from sleep based on predefined conditions, and thus allows some internal operation like DMA transfer and/or the CPU to wake up only when needed, e.g. when a threshold is crossed or a result is ready. The Event System supports synchronous and asynchronous events, allowing peripherals to receive, react to and send events even in standby mode.

The SAM L22 devices have two software-selectable performance level (PL0 and PL2) allowing the user to scale the lowest core voltage level that will support the operating frequency.

The Flash program memory can be reprogrammed in-system through the SWD interface. The same interface can be used for nonintrusive on-chip debugging of application code. A boot loader running in the device can use any communication interface to download and upgrade the application program in the Flash memory.

The Atmel SAM L22 devices are supported with a full suite of program and system development tools, including C compilers, macro assemblers, program debugger/simulators, programmers and evaluation kits.

2. Configuration Summary

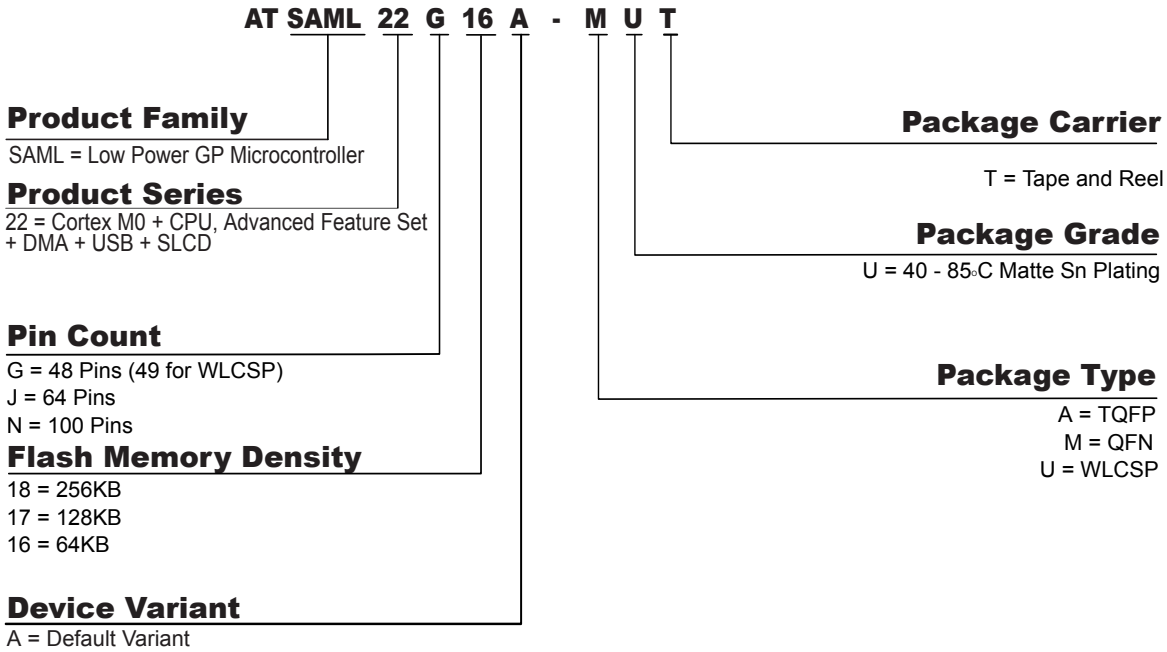
	SAM L22N	SAM L22J	SAM L22G
Pins	100	64	48 (QFN and TQFP) 49 (WLCSP)
General Purpose I/O-pins (GPIOs)[1]	82	50	36
Flash	256/128/64KB	256/128/64KB	256/128/64KB
Flash RWW section	8/4/2KB	8/4/2KB	8/4/2KB
System SRAM	32/16/8KB	32/16/8KB	32/16/8KB
Segment LCD (SLCD) Pins[1]	48 selectable from 52	31	23
Timer Counter (TC) instances	4	4	4
Waveform output channels per TC instance	2	2	2
Timer Counter for Control (TCC) instances	1	1	1
Waveform output channels per TCC	4	4	4
DMA channels	16	16	16
USB interface	1	1	1
AES engine	1	1	1
Configurable Custom Logic (CCL) (LUTs)	4	4	4
True Random Generator (TRNG)	1	1	1
Serial Communication Interface (SERCOM) instances	6	4[2]	4[2]
Analog-to-Digital Converter (ADC) channels	20	16	10
Two Analog Comparators (AC) with number of external input channels	4	4	2
Tamper Input Pins	5	3	2

	SAM L22N	SAM L22J	SAM L22G
Wake-up Pins with debouncing	5	3	2
Real-Time Counter (RTC)	Yes	Yes	Yes
RTC alarms	1	1	1
RTC compare values	One 32-bit value or two 16-bit values	One 32-bit value or two 16-bit values	One 32-bit value or two 16-bit values
External Interrupt lines	16	16	16
Peripheral Touch Controller (PTC) channels (X- x Y-lines) for mutual capacitance[3]	256 (16x16)	182 (13x14)	132 (11x12)
Peripheral Touch Controller (PTC) channels for self capacitance (Y-lines only)[4]	24	19	15
Maximum CPU frequency	32MHz	32MHz	32MHz
Packages	TQFP	QFN TQFP	QFN TQFP WLCSP
Oscillators			
Event System channels	8	8	8
SW Debug Interface	Yes	Yes	Yes
Watchdog Timer (WDT)	Yes	Yes	Yes

Note:

1. L22J, L22G: All SLCD Pins can be configured also as GPIOs. L22N: 44 SLCD Pins can be configured as GPIOs, 8 SLCD Pins can be used as GP input.
2. SAM L22N: SERCOM[5:0]. L22G, L22J: SERCOM[3:0].
3. The number of X- and Y-lines depends on the configuration of the device, as some I/O lines can be configured as either X-lines or Y-lines.
4. The number of Y-lines depends on the configuration of the device, as some I/O lines can be configured as either X-lines or Y-lines. The number given here is the maximum number of Y-lines that can be obtained.

3. Ordering Information



Note: The device variant (last letter of the ordering number) is independent of the die revision (DSU.DID.REVISION): The device variant denotes functional differences, whereas the die revision marks evolution of the die.

3.1. SAM L22N

Table 3-1. SAM L22N Ordering Codes

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAML22N16A-AUT	64K	8K	TQFP100	Tape & Reel
ATSAML22N17A-AUT	128K	16K	TQFP100	Tape & Reel
ATSAML22N18A-AUT	256K	32K	TQFP100	Tape & Reel

3.2. SAM L22J

Table 3-2. SAM L22J Ordering Codes

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAML22J16A-AUT	64K	8K	TQFP64	Tape & Reel
ATSAML22J16A-MUT			QFN64	
ATSAML22J17A-AUT	128K	16K	TQFP64	Tape & Reel
ATSAML22J17A-MUT			QFN64	

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAML22J18A-AUT	256K	32K	TQFP64	Tape & Reel
ATSAML22J18A-MUT			QFN64	

3.3. SAM L22G

Table 3-3. SAM L22G Ordering Codes

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAML22G16A-AUT	64K	8K	TQFP48	Tape & Reel
ATSAML22G16A-MUT			QFN48	
ATSAML22G17A-AUT	128K	16K	TQFP48	Tape & Reel
ATSAML22G17A-MUT			QFN48	
ATSAML22G17A-UUT			WLCSP49	
ATSAML22G18A-AUT	256K	32K	TQFP48	Tape & Reel
ATSAML22G18A-MUT			QFN48	
ATSAML22G18A-UUT			WLCSP49	

3.4. Device Identification

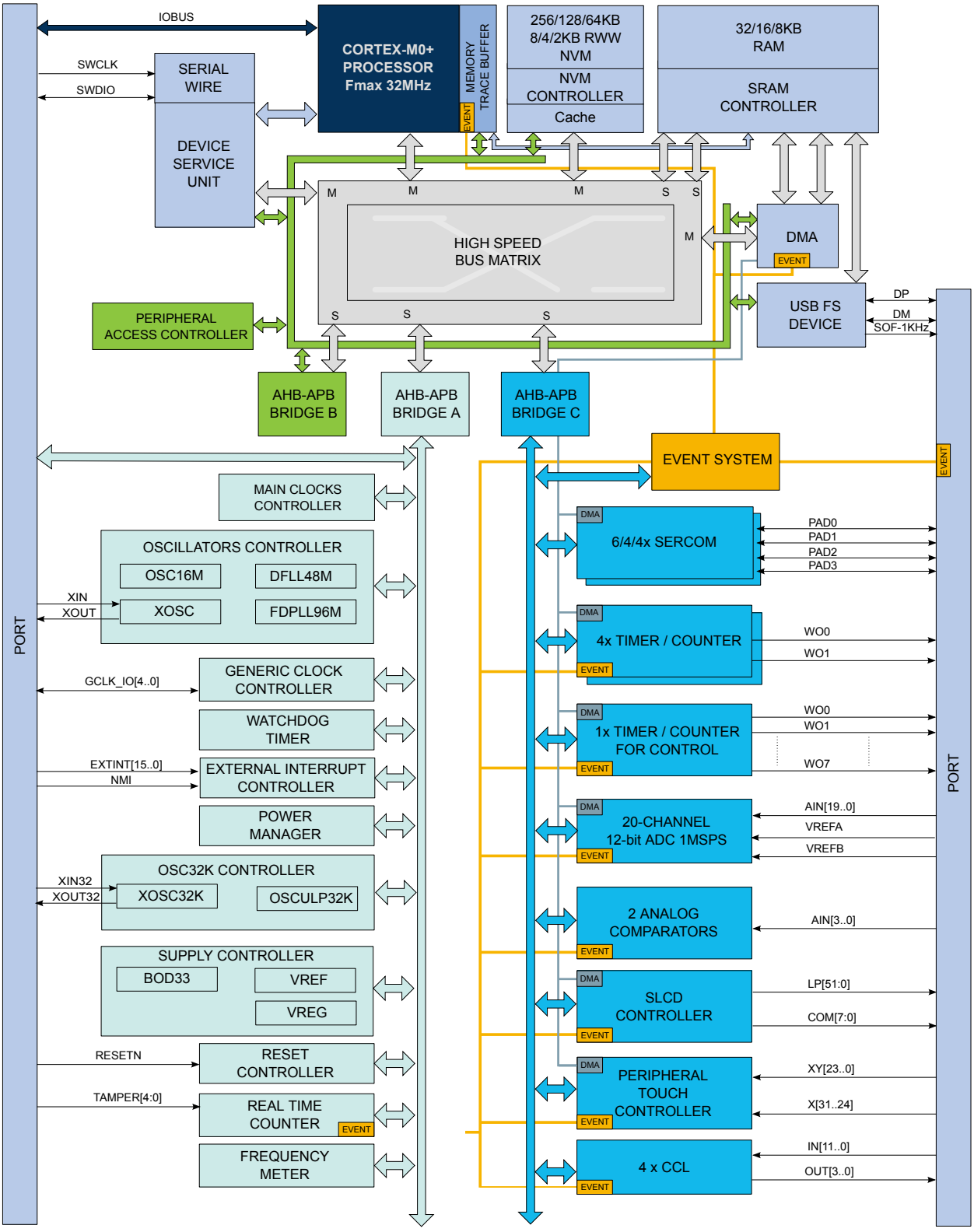
The DSU - Device Service Unit peripheral provides the Device Selection bits in the Device Identification register (DID.DEVSEL) in order to identify the device by software. The SAM L22 variants have a reset value of DID=0x10820xxx, with the last digits identifying the variant:

Table 3-4. SAM L22 Device Identification Values

DSU DID.DEVSEL	Device
0x0	L22N18
0x1	L22N17
0x2	L22N16
0x3-0x4	Reserved
0x5	L22J18
0x6	L22J17
0x7	L22J16
0x8-0x9	Reserved
0xA	L22G18
0xB	L22G17
0xC	L22G16
0xD-0xFF	Reserved

Note: The device variant (last letter of the ordering number) is independent of the die revision (DSU.DID.REVISION): The device variant denotes functional differences, whereas the die revision marks evolution of the die.

4. Block Diagram



Note:

1. Some device configurations have different number of SERCOM instances, Timer/Counter instances, PTC signals and ADC signals. The number of PTC X and Y signals is configurable.

5. Pinout

5.1. SAM L22G

Figure 5-1. 48-Pin QFN, TQFP

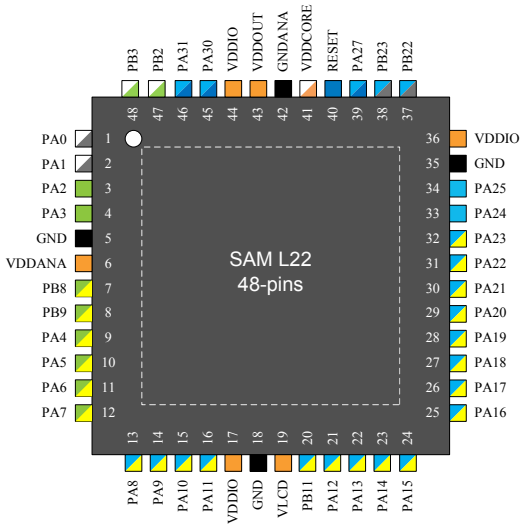
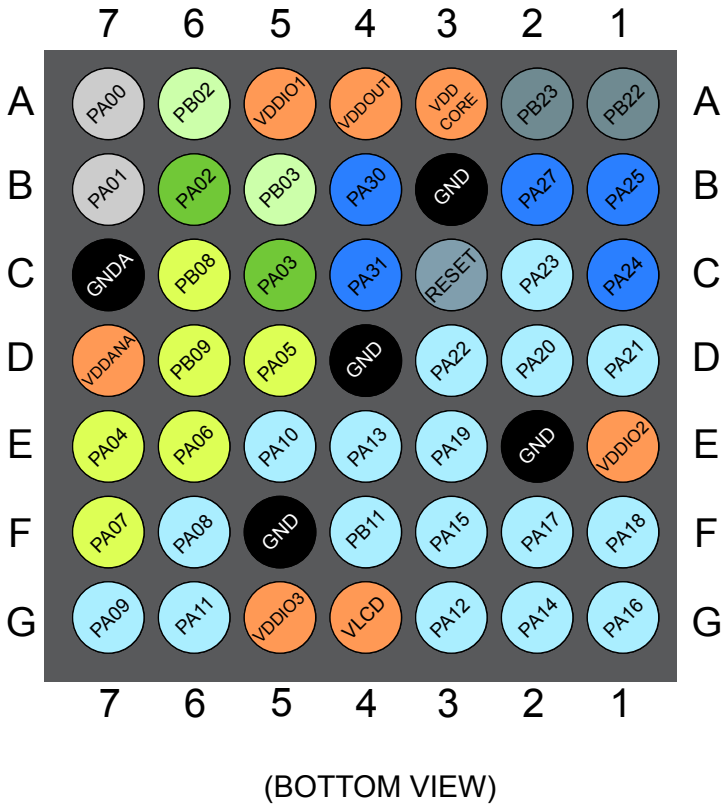
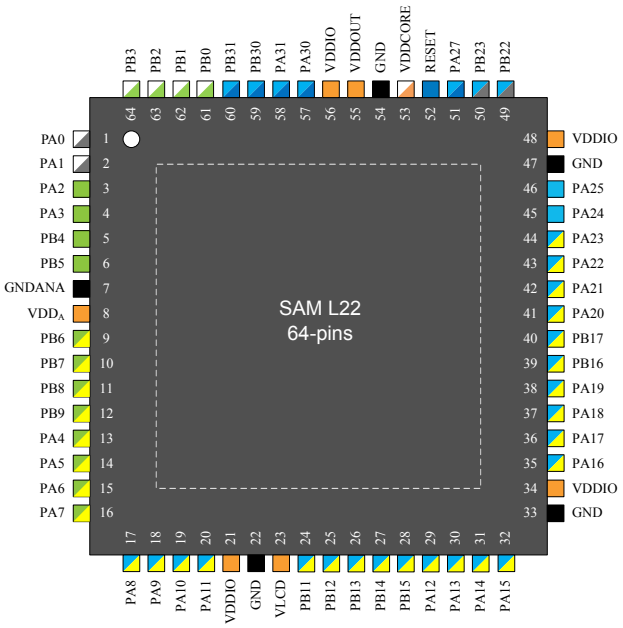


Figure 5-2. 49-Pin WLCSP

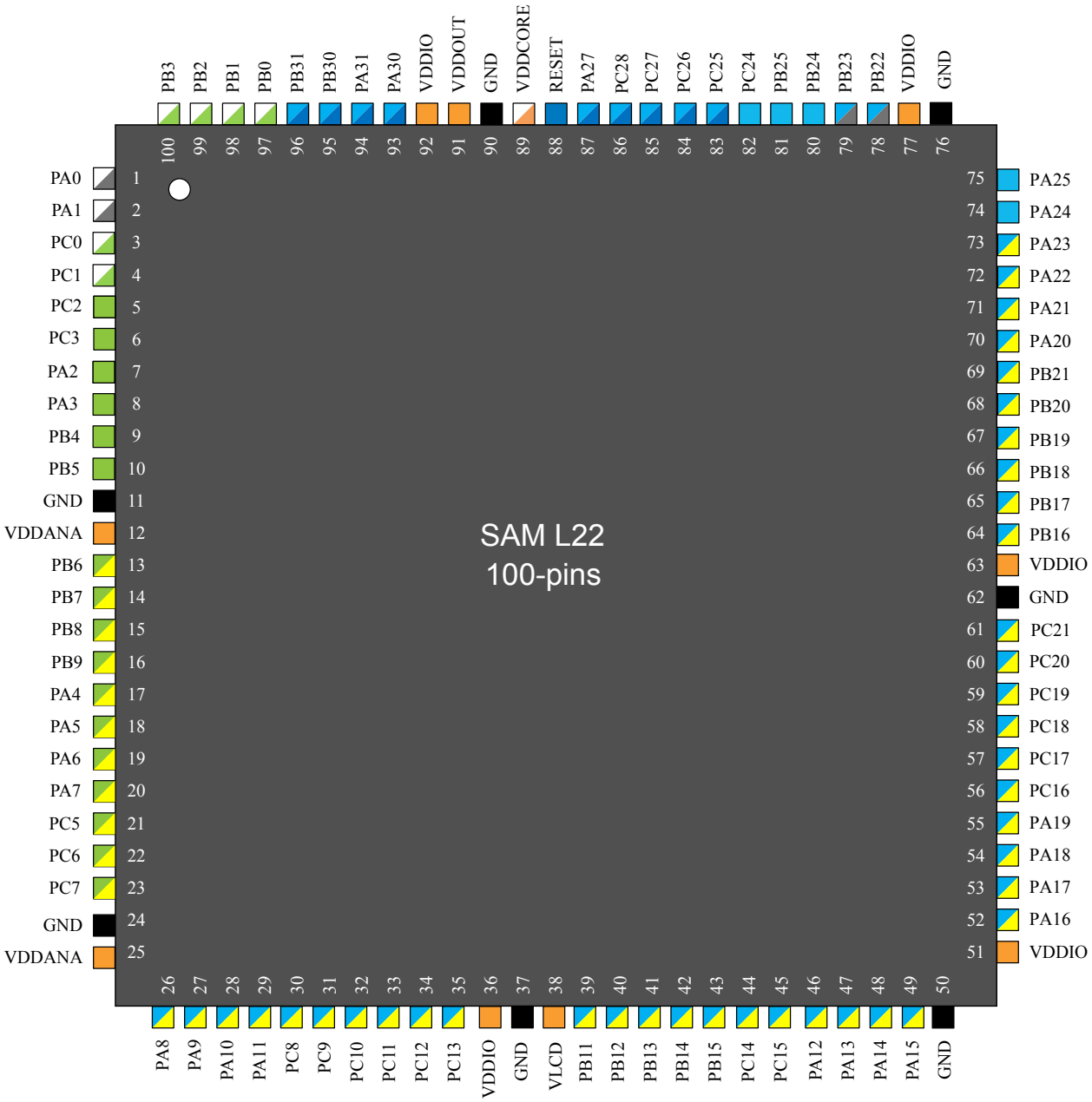


(BOTTOM VIEW)

5.2. SAM L22J


SAM L22
64-pins
PB3 64
PB2 63
PB1 62
PB0 61
PB31 60
PB30 59
PA31 58
PA30 57
VDDIO 56
VDDOUT 55
GND 54
VDDCORE 53
RESET 52
PA27 51
PB23 50
PB22 49
PA0 1
PA1 2
PA2 3
PA3 4
PB4 5
PB5 6
GNDANA 7
VDDA 8
PB6 9
PB7 10
PB8 11
PB9 12
PA4 13
PA5 14
PA6 15
PA7 16
48 VDDIO
47 GND
46 PA25
45 PA24
44 PA23
43 PA22
42 PA21
41 PA20
40 PB17
39 PB16
38 PA19
37 PA18
36 PA17
35 PA16
34 VDDIO
33 GND
17 PA8
18 PA9
19 PA10
20 PA11
21 VDDIO
22 GND
23 VLCD
24 PB11
25 PB12
26 PB13
27 PB14
28 PB15
29 PA12
30 PA13
31 PA14
32 PA15

5.3. SAM L22N


SAM L22
100-pins
PB3 100
PB2 99
PB1 98
PB0 97
PB31 96
PB30 95
PA31 94
PA30 93
VDDIO 92
VDDOUT 91
GND 90
VDDCORE 89
RESET 88
PA27 87
PC28 86
PC27 85
PC26 84
PC25 83
PC24 82
PB25 81
PB24 80
PB23 79
PB22 78
VDDIO 77
GND 76
PA0 1
PA1 2
PC0 3
PC1 4
PC2 5
PC3 6
PA2 7
PA3 8
PB4 9
PB5 10
GND 11
VDDANA 12
PB6 13
PB7 14
PB8 15
PB9 16
PA4 17
PA5 18
PA6 19
PA7 20
PC5 21
PC6 22
PC7 23
GND 24
VDDANA 25
75 PA25
74 PA24
73 PA23
72 PA22
71 PA21
70 PA20
69 PB21
68 PB20
67 PB19
66 PB18
65 PB17
64 PB16
63 VDDIO
62 GND
61 PC21
60 PC20
59 PC19
58 PC18
57 PC17
56 PC16
55 PA19
54 PA18
53 PA17
52 PA16
51 VDDIO
26 PA8
27 PA9
28 PA10
29 PA11
30 PC8
31 PC9
32 PC10
33 PC11
34 PC12
35 PC13
36 VDDIO
37 GND
38 VLCD
39 PB11
40 PB12
41 PB13
42 PB14
43 PB15
44 PC14
45 PC15
46 PA12
47 PA13
48 PA14
49 PA15
50 GND

6. Signal Descriptions List

The following table gives details on signal names classified by peripheral.

Table 6-1. Signal Descriptions List

Signal Name	Function	Type	Active Level
Analog Comparators - AC			
AIN[3:0]	AC Analog Inputs	Analog	
CMP[1:0]	AC Analog Output	Analog	
Analog Digital Converter - ADC			
AIN[19:0]	ADC Analog Inputs	Analog	
VREFA	ADC Voltage External Reference A	Analog	
VREFB	ADC Voltage External Reference B	Analog	
External Interrupt Controller - EIC			
EXTINT[15:0]	External Interrupts inputs	Digital	
NMI	External Non-Maskable Interrupt input	Digital	
Generic Clock Generator - GCLK			
GCLK_IO[4:0]	Generic Clock (source clock inputs or generic clock generator output)	Digital	
Custom Control Logic - CCL			
IN[11:0]	Logic Inputs	Digital	
OUT[3:0]	Logic Outputs	Digital	
Supply Controller - SUPC			
VBAT	External battery supply Inputs	Analog	
PSOK	Main Power Supply OK input	Digital	
OUT[1:0]	Logic Outputs	Digital	
Power Manager - PM			
RESETN	Reset input	Digital	Low
Serial Communication Interface - SERCOMx			
PAD[3:0]	SERCOM Inputs/Outputs Pads	Digital	
Oscillators Control - OSCCTRL			
XIN	Crystal or external clock Input	Analog/Digital	
XOUT	Crystal Output	Analog	

Signal Name	Function	Type	Active Level
32KHz Oscillators Control - OSC32KCTRL			
XIN32	32KHz Crystal or external clock Input	Analog/Digital	
XOUT32	32KHz Crystal Output	Analog	
Timer Counter - TCx			
WO[1:0]	Waveform Outputs	Digital	
Timer Counter - TCCx			
WO[7:0]	Waveform Outputs	Digital	
Peripheral Touch Controller - PTC			
X[7:0]	PTC Input/Output	Analog	
Y[23:0]	PTC Input/Output	Analog	
X[31:24]	PTC Output	Analog	
General Purpose I/O - PORT			
PA25 - PA00	Parallel I/O Controller I/O Port A	Digital	
PA27	Parallel I/O Controller I/O Port A	Digital	
PA31 - PA30	Parallel I/O Controller I/O Port A	Digital	
PB09 - PB00	Parallel I/O Controller I/O Port B	Digital	
PB25 - PB11	Parallel I/O Controller I/O Port B	Digital	
PB31 - PB30	Parallel I/O Controller I/O Port B	Digital	
PC03 - PC00	Parallel I/O Controller I/O Port C	Digital	
PC07 - PC05	Parallel I/O Controller I/O Port C	Digital	
PC17 - PC12	Parallel I/O Controller I/O Port C	Digital	
PC28 - PC24	Parallel I/O Controller I/O Port C	Digital	
General Purpose input - PORT			
PC11 - PC08	Parallel I/O Controller input Port C	Digital	
PC21 - PC18	Parallel I/O Controller input Port C	Digital	
Segment LCD			
SLCD51 - SLCD00	Segment LCD	Analog	
VLCD	Bias Voltage	Analog	
Universal Serial Bus - USB			
DP	DP for USB	Digital	
DM	DM for USB	Digital	

Signal Name	Function	Type	Active Level
SOF 1kHz	USB Start of Frame	Digital	
Real Timer Clock - RTC			
RTC_IN[4:0]	Tamper or external wake-up pins	Digital	
RTC_OUT	Tamper output	Digital	

7. I/O Multiplexing and Considerations

7.1. Multiplexed Signals

Each pin is by default controlled by the PORT as a general purpose I/O and alternatively it can be assigned a different peripheral functions. To enable a peripheral function on a pin, the Peripheral Multiplexer Enable bit in the Pin Configuration register corresponding to that pin (PINCFGn.PMUXEN, n = 0-31) in the PORT must be written to '1'. The selection of peripheral function A to I is done by writing to the Peripheral Multiplexing Odd and Even bits in the Peripheral Multiplexing register (PMUXn.PMUXE/O) of the PORT.

This table describes the peripheral signals multiplexed to the PORT I/O pins.

Table 7-1. PORT Function Multiplexing

Function	-				A	B					C	D	E		F	H	I
Type	L22G[5]	L22J	L22N	Pad Name	EIC	ANAREF	ADC	AC	PTC	SLCD	SERCOM[6]	SERCOM[6]	TC/TCC	TCC/RTC	COM/RTC	AC/ GCLK/ SUPC	CCL
Battery backup	1	1	1	PA00	EIC/EXTINT[0]							SERCOM1/ PAD[0]					
	2	2	2	PA01	EIC/EXTINT[1]							SERCOM1/ PAD[1]					
			3	PC00	EIC/EXTINT[8]		ADC/ AIN[16]								RTC/IN[3]		
			4	PC01	EIC/EXTINT[9]		ADC/ AIN[17]								RTC/IN[4]		
			5	PC02	EIC/EXTINT[10]		ADC/ AIN[18]		PTC/ XY[6]								
			6	PC03	EIC/EXTINT[11]		ADC/ AIN[19]		PTC/ XY[7]								
	3	3	7	PA02	EIC/EXTINT[2]	ADC/ VREFB	ADC/ AIN[0]	AC/ AIN[0]	PTC/ XY[8]						RTC/IN[2]		
	4	4	8	PA03	EIC/EXTINT[3]	ADC/ VREFA	ADC/ AIN[1]	AC/ AIN[1]	PTC/ XY[9]								
		5	9	PB04	EIC/EXTINT[4]		ADC/ AIN[12]	AC/ AIN[2]	PTC/ XY[10]								
		6	10	PB05	EIC/EXTINT[5]		ADC/ AIN[13]	AC/ AIN[3]	PTC/ XY[11]								
		9	13	PB06	EIC/EXTINT[6]		ADC/ AIN[14]		PTC/ XY[12]	SLCD/ LP[0]							CCL/IN[6]
		10	14	PB07	EIC/EXTINT[7]		ADC/ AIN[15]		PTC/ XY[13]	SLCD/ LP[1]							CCL/IN[7]
	7	11	15	PB08	EIC/EXTINT[8]		ADC/ AIN[2]		PTC/ XY[14]	SLCD/ LP[2]		SERCOM3/ PAD[0]	TC/0/ WO[0]				CCL/IN[8]
	8	12	16	PB09	EIC/EXTINT[9]		ADC/ AIN[3]		PTC/ XY[15]	SLCD/ LP[3]		SERCOM3/ PAD[1]	TC/0/ WO[1]				CCL/ OUT[2]
	9	13	17	PA04	EIC/EXTINT[4]		ADC/ AIN[4]		PTC/ X[24]	SLCD/ LP[4]		SERCOM0/ PAD[0]	TCC/ WO[0]				CCL/IN[0]
	10	14	18	PA05	EIC/EXTINT[5]		ADC/ AIN[5]		PTC/ X[25]	SLCD/ LP[5]		SERCOM0/ PAD[1]	TCC/ WO[1]				CCL/IN[1]
	11	15	19	PA06	EIC/EXTINT[6]		ADC/ AIN[6]		PTC/ X[26]	SLCD/ LP[6]		SERCOM0/ PAD[2]					CCL/IN[2]
	12	16	20	PA07	EIC/EXTINT[7]		ADC/ AIN[7]		PTC/ X[27]	SLCD/ LP[7]		SERCOM0/ PAD[3]					CCL/ OUT[0]
			21	PC05	EIC/EXTINT[13]				PTC/ XY[4]	SLCD/ LP[8]							
			22	PC06	EIC/EXTINT[14]				PTC/ XY[5]	SLCD/ LP[9]							
			23	PC07	EIC/EXTINT[15]					SLCD/ LP[10]							
	13	17	26	PA08	EIC/NMI				PTC/ XY[3]	SLCD/ LP[11]	SERCOM0/ PAD[0]	SERCOM4/ PAD[0]	TCC/ WO[0]				CCL/IN[3]
	14	18	27	PA09	EIC/EXTINT[9]				PTC/ XY[2]	SLCD/ LP[12]	SERCOM0/ PAD[1]	SERCOM4/ PAD[1]	TCC/ WO[1]				CCL/IN[4]
	15	19	28	PA10	EIC/EXTINT[10]				PTC/ XY[1]	SLCD/ LP[13]	SERCOM0/ PAD[2]	SERCOM4/ PAD[2]		TCC/ WO[2]		GCLK/ IO[4]	CCL/IN[5]
	16	20	29	PA11	EIC/EXTINT[11]				PTC/ XY[0]	SLCD/ LP[14]	SERCOM0/ PAD[3]	SERCOM4/ PAD[3]		TCC/ WO[3]			CCL/ OUT[1]

Function	-				A	B					C	D	E		F	H	I
Type	L22G[5]	L22J	L22N	Pad Name	EIC	ANAREF	ADC	AC	PTC	SLCD	SERCOM[6]	SERCOM[6]	TC/TCC	TCC/RTC	COM/RTC	AC/ GCLK/ SUPC	CCL
digital: input only			30	PC08	EIC/EXTINT[0]					SLCD/ LP[15]							
			31	PC09	EIC/EXTINT[1]					SLCD/ LP[16]							
			32	PC10	EIC/EXTINT[2]					SLCD/ LP[17]	SERCOM1/ PAD[2]						
			33	PC11	EIC/EXTINT[3]					SLCD/ LP[18]	SERCOM1/ PAD[3]						
			34	PC12	EIC/EXTINT[4]					SLCD/ LP[19]	SERCOM1/ PAD[0]						
			35	PC13	EIC/EXTINT[5]					SLCD/ LP[20]	SERCOM1/ PAD[1]						
	19	23	38	VLCD													
	20	24	39	PB11	EIC/EXTINT[11]					SLCD/ LP[21]		SERCOM3/ PAD[3]	TC/1/ WO[1]	TCC/ WO[5]			CCL/ OUT[1]
I2C: full Fm+. Limited currents for Sm, Fm		25	40	PB12	EIC/EXTINT[12]					SLCD/ LP[22]	SERCOM3/ PAD[0]		TC/0/ WO[0]	TCC/ WO[6]			
		26	41	PB13	EIC/EXTINT[13]					SLCD/ LP[23]	SERCOM3/ PAD[1]		TC/0/ WO[1]	TCC/ WO[7]			
		27	42	PB14	EIC/EXTINT[14]					SLCD/ LP[24]	SERCOM3/ PAD[2]		TC/1/ WO[0]			GCLK/ IO[0]	CCL/IN[9]
		28	43	PB15	EIC/EXTINT[15]					SLCD/ LP[25]	SERCOM3/ PAD[3]		TC/1/ WO[1]			GCLK/ IO[1]	CCL/ IN[10]
			44	PC14	EIC/EXTINT[6]					SLCD/ LP[26]							
			45	PC15	EIC/EXTINT[7]					SLCD/ LP[27]							
I2C: Sm, Fm, Fm+	21	29	46	PA12	EIC/EXTINT[12]					SLCD/ LP[28]	SERCOM4/ PAD[0]	SERCOM3/ PAD[0]		TCC/ WO[6]		AC/ CMP[0]	
	22	30	47	PA13	EIC/EXTINT[13]					SLCD/ LP[29]	SERCOM4/ PAD[1]	SERCOM3/ PAD[1]		TCC/ WO[7]		AC/ CMP[1]	
	23	31	48	PA14	EIC/EXTINT[14]					SLCD/ LP[30]	SERCOM4/ PAD[2]	SERCOM3/ PAD[2]		TCC/ WO[4]		GCLK/ IO[0]	
	24	32	49	PA15	EIC/EXTINT[15]					SLCD/ LP[31]	SERCOM4/ PAD[3]	SERCOM3/ PAD[3]		TCC/ WO[5]		GCLK/ IO[1]	
	25	35	52	PA16	EIC/EXTINT[0]				PTC/ X[28]	SLCD/ LP[32]	SERCOM1/ PAD[0]	SERCOM2/ PAD[0]		TCC/ WO[6]		GCLK/ IO[2]	CCL/IN[0]
	26	36	53	PA17	EIC/EXTINT[1]				PTC/ X[29]	SLCD/ LP[33]	SERCOM1/ PAD[1]	SERCOM2/ PAD[1]		TCC/ WO[7]		GCLK/ IO[3]	CCL/IN[1]
	27	37	54	PA18	EIC/EXTINT[2]				PTC/ X[30]	SLCD/ LP[34]	SERCOM1/ PAD[2]	SERCOM2/ PAD[2]		TCC/ WO[2]		AC/ CMP[0]	CCL/IN[2]
	28	38	55	PA19	EIC/EXTINT[3]				PTC/ X[31]	SLCD/ LP[35]	SERCOM1/ PAD[3]	SERCOM2/ PAD[3]		TCC/ WO[3]		AC/ CMP[1]	CCL/ OUT[0]
			56	PC16	EIC/EXTINT[8]					SLCD/ LP[36]							
			57	PC17	EIC/EXTINT[9]					SLCD/ LP[37]							
digital: input only			58	PC18	EIC/EXTINT[10]					SLCD/ LP[38]							
			59	PC19	EIC/EXTINT[11]					SLCD/ LP[39]							
			60	PC20	EIC/EXTINT[12]					SLCD/ LP[40]							CCL/IN[9]
			61	PC21	EIC/EXTINT[13]					SLCD/ LP[41]							CCL/ IN[10]
		39	64	PB16	EIC/EXTINT[0]					SLCD/ LP[42]	SERCOM5/ PAD[0]		TC/2/ WO[0]	TCC/ WO[4]		GCLK/ IO[2]	CCL/IN[11]
		40	65	PB17	EIC/EXTINT[1]					SLCD/ LP[43]	SERCOM5/ PAD[1]		TC/2/ WO[1]	TCC/ WO[5]		GCLK/ IO[3]	CCL/ OUT[3]
			66	PB18	EIC/EXTINT[2]					SLCD/ LP[44]	SERCOM5/ PAD[2]	SERCOM3/ PAD[2]		TCC/ WO[0]			
			67	PB19	EIC/EXTINT[3]					SLCD/ LP[45]	SERCOM5/ PAD[3]	SERCOM3/ PAD[3]		TCC/ WO[1]			
			68	PB20	EIC/EXTINT[4]					SLCD/ LP[46]	SERCOM3/ PAD[0]	SERCOM5/ PAD[0]		TCC/ WO[2]			
			69	PB21	EIC/EXTINT[5]					SLCD/ LP[47]	SERCOM3/ PAD[1]	SERCOM5/ PAD[1]		TCC/ WO[3]			
	29	41	70	PA20	EIC/EXTINT[4]				PTC/ XY[16]	SLCD/ LP[48]	SERCOM0/ PAD[0]	SERCOM2/ PAD[2]	TC/3/ WO[0]	TCC/ WO[6]		GCLK/ IO[4]	
	30	42	71	PA21	EIC/EXTINT[5]				PTC/ XY[17]	SLCD/ LP[49]	SERCOM0/ PAD[1]	SERCOM2/ PAD[3]	TC/3/ WO[1]	TCC/ WO[7]			
I2C: Sm, Fm, Fm+	31	43	72	PA22	EIC/EXTINT[6]				PTC/ XY[18]	SLCD/ LP[50]	SERCOM0/ PAD[2]	SERCOM2/ PAD[0]	TC/0/ WO[0]	TCC/ WO[4]			CCL/IN[6]
	32	44	73	PA23	EIC/EXTINT[7]				PTC/ XY[19]	SLCD/ LP[51]	SERCOM0/ PAD[3]	SERCOM2/ PAD[1]	TC/0/ WO[1]	TCC/ WO[5]	USB/SOF_1KHZ		CCL/IN[7]
	33	45	74	PA24	EIC/EXTINT[12]						SERCOM2/ PAD[2]	SERCOM5/ PAD[0]	TC/1/ WO[0]	TCC/ WO[0]	USB/DM		CCL/IN[8]
	34	46	75	PA25	EIC/EXTINT[13]						SERCOM2/ PAD[3]	SERCOM5/ PAD[1]	TC/1/ WO[1]	TCC/ WO[1]	USB/DP		CCL/ OUT[2]
	37	49	78	PB22	EIC/EXTINT[6]						SERCOM0/ PAD[2]	SERCOM5/ PAD[2]	TC/3/ WO[0]	TCC/ WO[2]	USB/SOF_1KHZ	GCLK/ IO[0]	CCL/IN[0]

Function	-				A	B					C	D	E		F	H	I
Type	L22G[5]	L22J	L22N	Pad Name	EIC	ANAREF	ADC	AC	PTC	SLCD	SERCOM[6]	SERCOM[6]	TC/TCC	TCC/RTC	COM/RTC	AC/ GCLK/ SUPC	CCL
	38	50	79	PB23	EIC/EXTINT[7]						SERCOM0/ PAD[3]	SERCOM5/ PAD[3]	TC/3/ WO[1]	TCC/ WO[3]		GCLK/ IO[1]	CCL/ OUT[0]
			80	PB24	EIC/EXTINT[8]						SERCOM0/ PAD[0]	SERCOM4/ PAD[0]		TCC/ WO[6]		AC/ CMP[0]	
			81	PB25	EIC/EXTINT[9]						SERCOM0/ PAD[1]	SERCOM4/ PAD[1]		TCC/ WO[7]		AC/ CMP[1]	
			82	PC24	EIC/EXTINT[0]						SERCOM0/ PAD[2]	SERCOM4/ PAD[2]	TC/2/ WO[0]	TCC/ WO[0]			
			83	PC25	EIC/EXTINT[1]						SERCOM0/ PAD[3]	SERCOM4/ PAD[3]	TC/2/ WO[1]	TCC/ WO[1]			
			84	PC26	EIC/EXTINT[2]								TC/3/ WO[0]	TCC/ WO[2]			
			85	PC27	EIC/EXTINT[3]							SERCOM1/ PAD[0]	TC/3/ WO[1]	TCC/ WO[3]			CCL/IN[4]
			86	PC28	EIC/EXTINT[4]				PTC/ XY[20]			SERCOM1/ PAD[1]		TCC/ WO[4]			CCL/IN[5]
recommended for GCLK IO	39	51	87	PA27	EIC/EXTINT[15]				PTC/ XY[21]					TCC/ WO[5]	TAL/BRK	GCLK/ IO[0]	
	40	52	88	RESET_N													
	45	57	93	PA30	EIC/EXTINT[10]				PTC/ XY[22]			SERCOM1/ PAD[2]			CORTEX_M0P/ SWCLK	GCLK/ IO[0]	CCL/IN[3]
	46	58	94	PA31	EIC/EXTINT[11]				PTC/ XY[23]			SERCOM1/ PAD[3]			SWDIO		CCL/ OUT[1]
I2C: Sm, Fm, Fm +, Hs		59	95	PB30	EIC/EXTINT[14]						SERCOM1/ PAD[0]	SERCOM5/ PAD[0]	TCC/ WO[0]				
		60	96	PB31	EIC/EXTINT[15]						SERCOM1/ PAD[1]	SERCOM5/ PAD[1]	TCC/ WO[1]				
Battery backup		61	97	PB00	EIC/EXTINT[0]		ADC/ AIN[8]				SERCOM3/ PAD[2]	SERCOM5/ PAD[2]	TC/3/ WO[0]		RTC/IN[0]	SUPC/ PSOK	CCL/IN[1]
		62	98	PB01	EIC/EXTINT[1]		ADC/ AIN[9]				SERCOM3/ PAD[3]	SERCOM5/ PAD[3]	TC/3/ WO[1]	RTC/IN[2]	RTC/OUT	SUPC/ OUT[0]	CCL/IN[2]
	47	63	99	PB02	EIC/EXTINT[2]		ADC/ AIN[10]				SERCOM3/ PAD[0]	SERCOM5/ PAD[0]	TC/2/ WO[0]		RTC/IN[1]	SUPC/ OUT[1]	CCL/ OUT[0]
	48	64	100	PB03	EIC/EXTINT[3]		ADC/ AIN[11]				SERCOM3/ PAD[1]	SERCOM5/ PAD[1]	TC/2/ WO[1]			SUPC/ VBAT	

Note:

1. All analog pin functions are on peripheral function B. Peripheral function B must be selected to disable the digital control of the pin.
2. Only some pins can be used in SERCOM I^2C mode. See the Type column for supported I^2C modes.
   - Sm: Standard mode, up to 100kHz
   - Fm: Fast mode, up to 400kHz
   - Fm+: Fast mode Plus, up to 1MHz
   - Hs: High-speed mode, up to 3.4MHz
3. These pins are High Sink pins and have different properties than regular pins: PA12, PA13, PA22, PA23, PA27, PA31, PB30, PB31.
4. Clusters of multiple GPIO pins are sharing the same supply pin.
5. The 49th pin of the WLCSP49 package is an additional GND pin.
6. SAM L22N: SERCOM[0:5]. SAM L22G, L22J: SERCOM[0:3].

Related Links

Configuration Summary on page 7
SERCOM USART and I2C Configurations on page 23

7.2. Other Functions

7.2.1. Oscillator Pinout

The oscillators are not mapped to the normal PORT functions and their multiplexing is controlled by registers in the Oscillators Controller (OSCCTRL) and in the 32K Oscillators Controller (OSC32KCTRL).

Table 7-2. Oscillator Pinout

Oscillator	Supply	Signal	I/O pin
XOSC	VDDIO	XIN	PB22
		XOUT	PB23
XOSC32K	VSWOUT	XIN32	PA00
		XOUT32	PA01

Note: In order to minimize the cycle-to-cycle jitter of the external oscillator, keep the neighboring pins as steady as possible. For neighboring pin details, refer to the Oscillator Pinout section.

Table 7-3. XOSC32K Jitter Minimization

Package	Steady Signal Recommended
L22N	PB00, PB01, PB02, PB03, PC00, PC01
L22J	PB00, PB01, PB02, PB03, PA02, PA03
L22G	PB02, PB03, PA02, PA03

7.2.2. Serial Wire Debug Interface Pinout

Only the SWCLK pin is mapped to the normal PORT functions. A debugger cold-plugging or hot-plugging detection will automatically switch the SWDIO port to the SWDIO function.

Table 7-4. Serial Wire Debug Interface Pinout

Signal	Supply	I/O pin
SWCLK	VDDIO	PA30
SWDIO	VDDIO	PA31

7.2.3. SERCOM USART and I²C Configurations

The SAM L22 has up to six instances of the serial communication interface (SERCOM) peripheral. The following table lists the supported communication protocols for each SERCOM instance.

Table 7-5. SERCOM USART and I²C Protocols

	SERCOM Instance					
Protocol	SERCOM0	SERCOM1	SERCOM2	SERCOM3	SERCOM4	SERCOM5
I²C	no	yes	yes	yes	yes	yes
I²C at 3.4MHz	no	yes	no	no	no	yes
USART including RS485 and ISO 7816	yes	yes	yes	yes	yes	yes
SPI	yes	yes	yes	yes	yes	yes

Note: Not all available I²C pins support I²C mode at 3.4MHz.

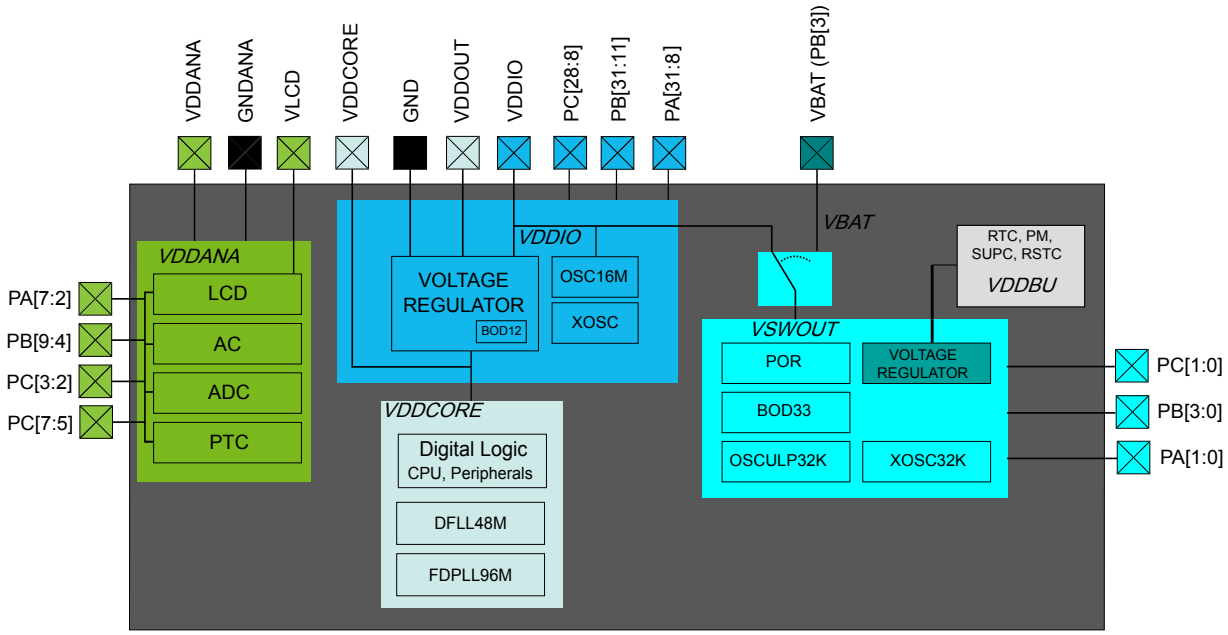
7.2.4. GPIO Pin Clusters

Table 7-6. GPIO Clusters

Package	Cluster	GPIO	Supplies Pin connected to the cluster	
100 pins	1	PA02, PA03, PB04, PB05, PC02, PC03	V_{DDANA} pin12	GNDANA pin11
	2	PA04, PA05, PA06, PA07, PB06, PB07, PB08, PB09, PC05, PC06, PC07	V_{DDANA} pin12, V_{DDANA} pin25	GNDANA pin11, GNDANA pin24
	3	PA08, PA09, PA10, PA11, PC08, PC09, PC10, PC11, PC12, PC13	V_{DDIO} pin36	GND pin37
	4	PA12, PA13, PA14, PA15, PB11, PB12, PB13, PB14, PB15, PC14, PC15	V_{DDIO} pin36, V_{DDIO} pin51	GND pin37, GND pin50
	5	PA16, PA17, PA18, PA19, PC16, PC17, PC18, PC19, PC20, PC21	V_{DDIO} pin51, V_{DDIO} pin63	GND pin50, GND pin62
	6	PA20, PA21, PA22, PA23, PA24, PA25, PB16, PB17, PB18, PB19, PB20, PB21	V_{DDIO} pin63, V_{DDIO} pin77	GND pin62, GND pin76
	7	PA27, PB22, PB23, PB24, PB25, PC24, PC25, PC26, PC27, PC28	V_{DDIO} pin77, V_{DDIO} pin92	GND pin76, GND pin90
	8	PA00, PA01, PA30, PA31, PB00, PB01, PB02, PB03, PB30, PB31, PC00, PC01	V_{DDIO} pin92	GND pin90
64 pins	1	PA02, PA03, PA04, PA05, PA06, PA07, PB04, PB05, PB06, PB07, PB08, PB09	V_{DDANA} pin8	GNDANA pin7
	2	PA08, PA09, PA10, PA11	V_{DDIO} pin21	GND pin22
	3	PA12, PA13, PA14, PA15, PB11, PB12, PB13, PB14, PB15	V_{DDIO} pin21, V_{DDIO} pin34	GND pin22, GND pin33
	4	PA16, PA17, PA18, PA19, PA20, PA21, PA22, PA23, PA24, PA25, PB16, PB17	V_{DDIO} pin34, V_{DDIO} pin48	GND pin33, GND pin47
	5	PA27, PB22, PB23	V_{DDIO} pin48, V_{DDIO} pin56	GND pin47, GND pin54
	6	PA00, PA01, PA30, PA31, PB00, PB01, PB02, PB03, PB30, PB31	V_{DDIO} pin56	GND pin54
48 pins	1	PA02, PA03, PA04, PA05, PA06, PA07, PB08, PB09	V_{DDANA} pin6	GNDANA pin5
	2	PA08, PA09, PA10, PA11	V_{DDIO} pin17	GND pin18
	3	PA12, PA13, PA14, PA15, PA16, PA17, PA18, PA19, PA20, PA21, PA22, PA23, PA24, PA25, PB11	V_{DDIO} pin17, V_{DDIO} pin36	GND pin18, GND pin35
	4	PA27, PB22, PB23	V_{DDIO} pin36, V_{DDIO} pin44	GND pin35, GND pin42
	5	PA00, PA01, PA30, PA31, PB02, PB03	V_{DDIO} pin44	GND pin42
49 pins	1	PA02, PA03, PA04, PA05, PA06, PA07, PB08, PB09	V_{DDANA} pin D7	GNDANA pin C7
	2	PA08, PA09, PA10, PA11	V_{DDIO} pin G5	GND pin F5
	3	PA12, PA13, PA14, PA15, PA16, PA17, PA18, PA19, PB11	V_{DDIO} pin G5, V_{DDIO} pin E1	GND pin F5, GND pin E2
	4	PA20, PA21, PA22, PA23, PA24, PA25	V_{DDIO} pin E1, V_{DDIO} pin A5	GND pin E2, GND pin D4
	4	PA27, PB22, PB23	V_{DDIO} pin E1, V_{DDIO} pin A5	GND pin D4, GND pin B3
	5	PA00, PA01, PA30, PA31, PB02, PB03	V_{DDIO} pin A5	GND pin B3

8. Power Supply and Start-Up Considerations

8.1. Power Domain Overview



The Atmel SAM L22 power domains are not independent of each other:

- VDDCORE and VDDIO share GND, whereas VDDANA refers to GNDANA.
- VDDCORE serves as the internal voltage regulator output.
- VSWOUT and VDDBU are internal power domains.

8.2. Power Supply Considerations

8.2.1. Power Supplies

The Atmel SAM L22 has several different power supply pins:

- VDDIO powers I/O lines and OSC16M, XOSC, the internal regulator for VDDCORE and the Automatic Power Switch. Voltage is 1.62V to 3.63V
- VDDANA powers I/O lines and the ADC, AC, LCD, and PTC. Voltage is 1.62V to 3.63V
- VLCD has two alternative functions:
  - Output of the LCD voltage pump when VLCD is generated internally. Output voltage is 2.5V to 3.5V.
  - Supply input for the bias generator when VLCD is provided externally by the application. Input voltage is 2.4 to 3.6V.
- VBAT powers the Automatic Power Switch. Voltage is 1.62V to 3.63V
- VDDCORE serves as the internal voltage regulator output. It powers the core, memories, peripherals, DFLL48M and FDPLL96M. Voltage is 0.9V to 1.2V typical.
- The Automatic Power Switch is a configurable switch that selects between VDDIO and VBAT as supply for the internal output VSWOUT, see the figure in Power Domain Overview.

The same voltage must be applied to both VDDIO and VDDANA. This common voltage is referred to as VDD in the datasheet.

The ground pins, GND, are common to VDDCORE, and VDDIO. The ground pin for VDDANA is GNDANA.

For decoupling recommendations for the different power supplies, refer to the schematic checklist.

8.2.2. Voltage Regulator

The SAM L22 internal Voltage Regulator has four different modes:

- Linear mode : This is the default mode when CPU and peripherals are running. It does not require an external inductor.
- Switching mode. This is the most efficient mode when the CPU and peripherals are running. This mode can be selected by software on the fly.
- Low Power (LP) mode. This is the default mode used when the chip is in standby mode.
- Shutdown mode. When the chip is in backup mode, the internal regulator is off.

Note that the Voltage Regulator modes are controlled by the Power Manager.

8.2.3. Typical Powering Schematic

The SAM L22 uses a single supply from 1.62V to 3.63V.

The following figure shows the recommended power supply connection.

Figure 8-1. Power Supply Connection for Linear Mode Only

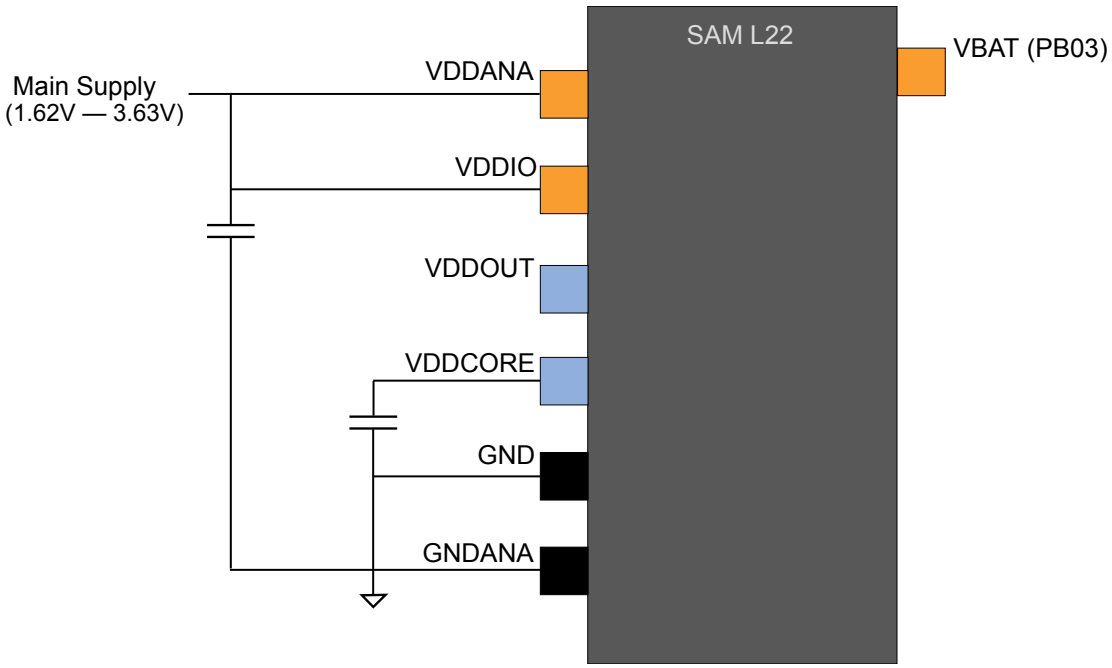


Figure 8-2. Power Supply Connection for Switching/Linear Mode

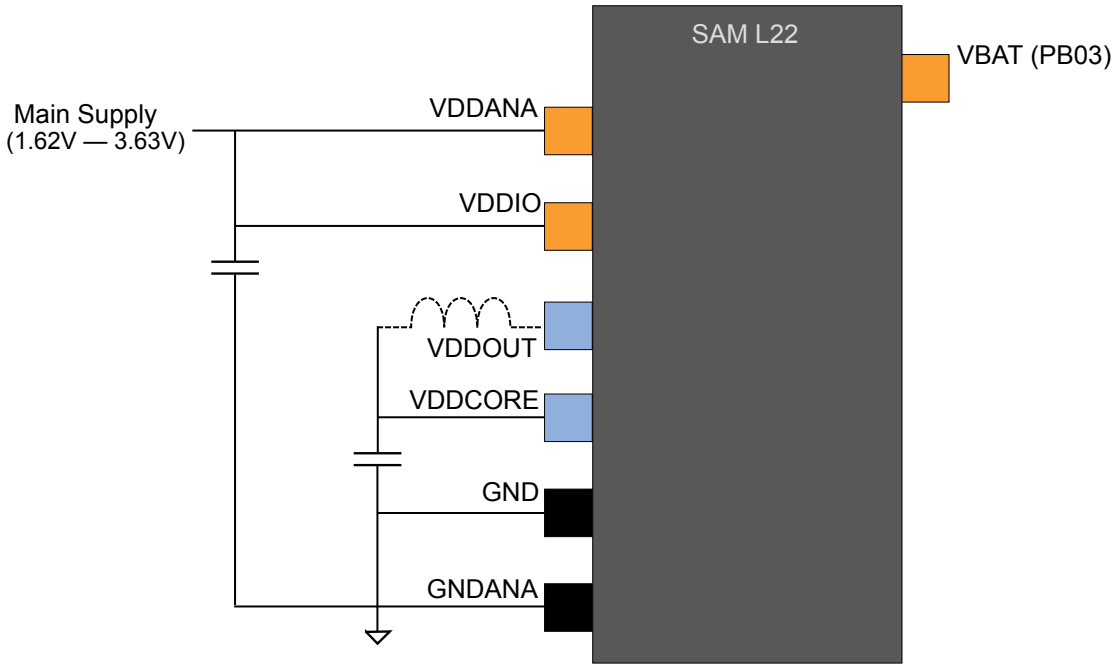
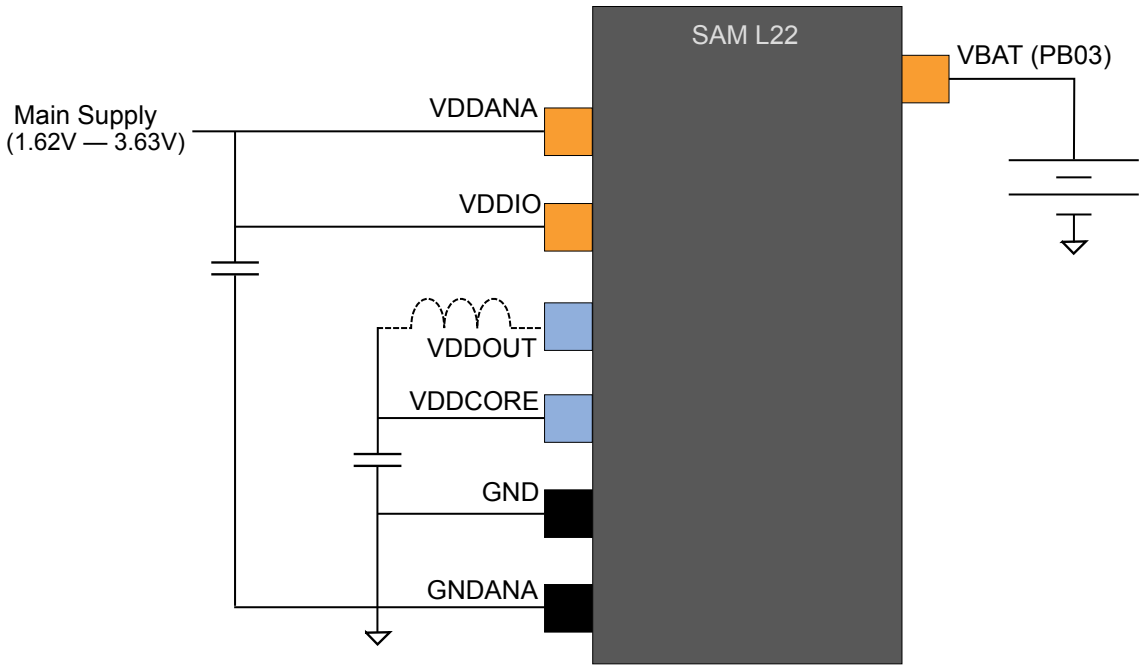


Figure 8-3. Power Supply Connection for Battery Backup



8.2.4. Power-Up Sequence

8.2.4.1. Supply Order

VDDIO and VDDANA must have the same supply sequence. Ideally, they must be connected together.

8.2.4.2. Minimum Rise Rate

One integrated power-on reset (POR) circuits monitoring VDDIO requires a minimum rise rate.

8.2.4.3. Maximum Rise Rate

The rise rate of the power supplies must not exceed the values described in Electrical Characteristics.

8.3. Power-Up

This section summarizes the power-up sequence of the SAM L22. The behavior after power-up is controlled by the Power Manager.

8.3.1. Starting of Internal Regulator

After power-up, the device is set to its initial state and kept in Reset, until the power has stabilized throughout the device. The default performance level after power-up is PL0.

The internal regulator provides the internal VDDCORE corresponding to this performance level. Once the external voltage VDDIO and the internal VDDCORE reach a stable value, the internal Reset is released.

8.3.2. Starting of Clocks

Once the power has stabilized and the internal Reset is released, the device will use a 4MHz clock by default. The clock source for this clock signal is OSC16M, which is enabled and configured at 4MHz after a reset by default. This is also the default time base for Generic Clock Generator 0. In turn, Generator 0 provides the main clock GCLK_MAIN which is used by the Power Manager (PM).

Some synchronous system clocks are active after Start-Up, allowing software execution. Refer to the “Clock Mask Register” section in the PM-Power Manager documentation for the list of clocks that are running by default. Synchronous system clocks that are running receive the 4MHz clock from Generic Clock Generator 0. Other generic clocks are disabled.

8.3.3. I/O Pins

After power-up, the I/O pins are tri-stated except PA30, which is pull-up enabled and configured as input.

8.3.4. Fetching of Initial Instructions

After Reset has been released, the CPU starts fetching PC and SP values from the Reset address, 0x00000000. This points to the first executable address in the internal Flash memory. The code read from the internal Flash can be used to configure the clock system and clock sources. See the related peripheral documentation for details. Refer to the ARM Architecture Reference Manual for more information on CPU startup (http://www.arm.com).

8.4. Power-On Reset and Brown-Out Detector

The SAM L22 embeds three features to monitor, warn and/or reset the device:

- POR: Power-on Reset on VSWOUT and VDDIO
- BOD33: Brown-out detector on VSWOUT/VBAT
- Brown-out detector internal to the voltage regulator for VDDCORE. BOD12 is calibrated in production and its calibration parameters are stored in the NVM User Row. This data should not be changed if the User Row is written to in order to assure correct behavior.

8.4.1. Power-On Reset on VSWOUT

VSWOUT is monitored by POR. Monitoring is always activated, including startup and all sleep modes. If VSWOUT goes below the threshold voltage, the entire chip is reset.

8.4.2. Power-On Reset on VDDIO

VDDIO is monitored by POR. Monitoring is always activated, including startup and all sleep modes. If VDDIO goes below the threshold voltage, all I/Os supplied by VDDIO are reset.

8.4.3. Brown-Out Detector on VSWOUT/VBAT

BOD33 monitors VSWOUT or VBAT depending on configuration.

8.4.4. Brown-Out Detector on VDDCORE

Once the device has started up, BOD12 monitors the internal VDDCORE.

8.5. Performance Level Overview

By default, the device will start in Performance Level 0. This PL0 is aiming for the lowest power consumption by limiting logic speeds and the CPU frequency. As a consequence, all GCLK will have limited capabilities, and some peripherals and clock sources will not work or with limited capabilities:

List of peripherals/clock sources not available in PL0:

- USB (limited by logic frequency)
- DFLL48M

List of peripherals/clock sources with limited capabilities in PL0:

- All AHB/APB peripherals are limited by CPU frequency
- DPLL96M: may be able to generate 48MHz internally, but the output cannot be used by logic
- GCLK: the maximum frequency is by factor 4 compared to PL2
- SW interface: the maximum frequency is by factor 4 compared to PL2
- TC: the maximum frequency is by factor 4 compared to PL2
- TCC:the maximum frequency is by factor 4 compared to PL2
- SERCOM: the maximum frequency is by factor 4 compared to PL2

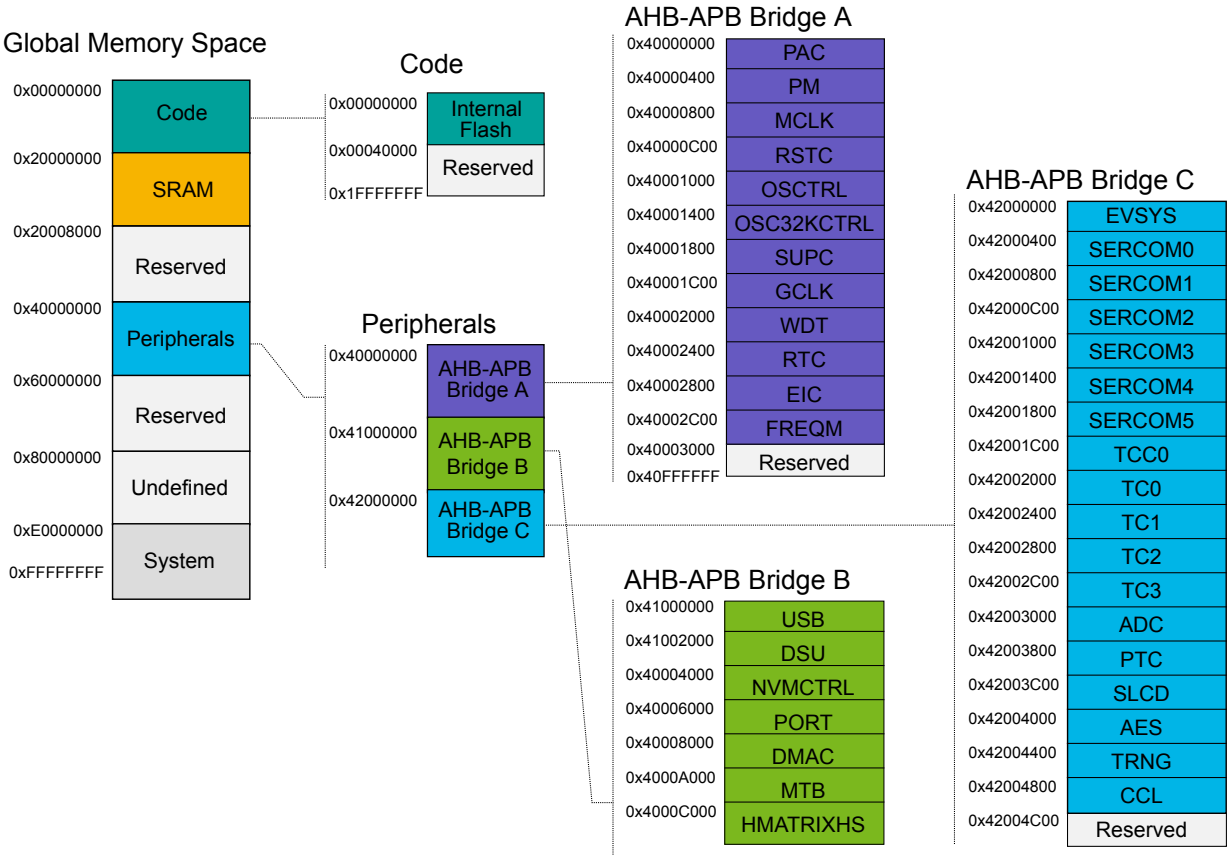
List of peripherals/clock sources with full capabilities in PL0:

- AC
- ADC
- EIC
- OSC16M
- PTC
- All 32KHz clock sources and peripherals

Full functionality and capability will be ensured in PL2. When transitioning between performance levels, the Supply Controller (SUPC) will provide a configurable smooth voltage scaling transition.

9. Product Mapping

Figure 9-1. Atmel SAM L22 Product Mapping



10. Memories

10.1. Embedded Memories

- Internal high-speed Flash with Read-While-Write (RWW) capability on a section of the array
- Internal high-speed RAM, single-cycle access at full speed

10.2. Physical Memory Map

The high-speed bus is implemented as a bus matrix. All high-speed bus addresses are fixed, and they are never remapped in any way, even during boot. The 32-bit physical address space is mapped as follows:

Table 10-1. SAM L22 Physical Memory Map

Memory	Start address	Size [KB]		
		SAML22x18(1)	SAML22x17(1)	SAML22x16(1)
Embedded Flash	0x00000000	256	128	64
Embedded RWW section	0x00400000	8	4	2
Embedded SRAM	0x20000000	32	16	8
Peripheral Bridge A	0x40000000	64	64	64
Peripheral Bridge B	0x41000000	64	64	64
Peripheral Bridge C	0x42000000	64	64	64
IOBUS	0x60000000	0.5	0.5	0.5

Note: 1. x = G, J, or E.

Table 10-2. Flash Memory Parameters

Device	Flash size [KB]	Number of pages	Page size [Bytes]
SAML22x18(1)	256	4096	64
SAML22x17(1)	128	2048	64
SAML22x16(1)	64	1024	64

Note: 1. x = G, J, or E.

Table 10-3. RWW Section Parameters(1)

Device	Flash size [KB]	Number of pages	Page size [Bytes]
SAML22x18(1)	8	128	64
SAML22x17(1)	4	64	64
SAML22x16(1)	2	32	64

Note: 1. x = G, J, or E.

10.3. NVM User Row Mapping

The Non Volatile Memory (NVM) User Row contains calibration data that are automatically read at device power-on.

The NVM User Row can be read at address 0x00804000.

To write the NVM User Row refer to the documentation of the NVMCTRL - Non-Volatile Memory Controller.

Note: When writing to the User Row, the new values do not get loaded by the other peripherals on the device until a device Reset occurs.

Table 10-4. NVM User Row Mapping

Bit Pos.	Name	Usage	Factory Setting	Related Peripheral Register
2:0	BOOTPROT	Used to select one of eight different bootloader sizes.	0x7	NVMCTRL
3	Reserved	—	0x1	—
6:4	EEPROM	Used to select one of eight different EEPROM sizes.	0x7	NVMCTRL
7	Reserved	—	0x1	—
13:8	BOD33 Level	BOD33 threshold level at power-on.	0x06	SUPC.BOD33
14	BOD33 Disable	BOD33 Disable at power-on.	0x0	SUPC.BOD33
16:15	BOD33 Action	BOD33 Action at power-on.	0x1	SUPC.BOD33
25:17	Reserved	Factory settings - do not change.	0x08F	-
26	WDT Enable	WDT Enable at power-on.	0x0	WDT.CTRLA
27	WDT Always-On	WDT Always-On at power-on.	0x0	WDT.CTRLA
31:28	WDT Period	WDT Period at power-on.	0xB	WDT.CONFIG
35:32	WDT Window	WDT Window mode time-out at power-on.	0xB	WDT.CONFIG
39:36	WDT EWOFFSET	WDT Early Warning Interrupt Time Offset at power-on.	0xB	WDT.EWCTRL
40	WDT WEN	WDT Timer Window Mode Enable at power-on.	0x0	WDT.CTRLA
41	BOD33 Hysteresis	BOD33 Hysteresis configuration at power-on.	0x0	SUPC.BOD33
47:42	Reserved	Factory settings - do not change.	0x3E	—
63:48	LOCK	NVM Region Lock Bits.	0xFFFF	NVMCTRL

10.4. NVM Software Calibration Area Mapping

The NVM Software Calibration Area contains calibration data that are determined and written during production test. These calibration values should be read by the application software and written back to the corresponding register.

The NVM Software Calibration Area can be read at address 0x00806020.

The NVM Software Calibration Area can not be written.

Table 10-5. NVM Software Calibration Area Mapping

Bit Position	Name	Description
2:0	ADC LINEARITY	ADC Linearity Calibration. Should be written to CALIB register.
5:3	ADC BIASCAL	ADC Bias Calibration. Should be written to CALIB register.
12:6	Reserved	Reserved for future use.
17:13	USB TRANSN	USB TRANSN calibration value. Should be written to the USB PADCAL register.
22:18	USB TRANSP	USB TRANSP calibration value. Should be written to the USB PADCAL register.
25:23	USB TRIM	USB TRIM calibration value. Should be written to the USB PADCAL register.
31:26	DFLL48M COARSE CAL	DFLL48M Coarse calibration value. Should be written to the OSCCTRL DFLLVAL register.

10.5. Serial Number

Each device has a unique 128-bit serial number which is a concatenation of four 32-bit words contained at the following addresses:

Word 0: 0x0080A00C

Word 1: 0x0080A040

Word 2: 0x0080A044

Word 3: 0x0080A048

The uniqueness of the serial number is guaranteed only when using all 128 bits.

11. Processor and Architecture

11.1. Cortex M0+ Processor

The Atmel SAM L22 implements the ARM ARM®Cortex™-M0+ processor, based on the ARMv6 Architecture and Thumb®-2 ISA. The Cortex M0+ is 100% instruction set compatible with its predecessor, the Cortex-M0 core, and upward compatible to Cortex-M3 and M4 cores. The implemented ARM Cortex-M0+ is revision r0p1. For more information refer to http://www.arm.com

11.1.1. Cortex M0+ Configuration

Table 11-1. Cortex M0+ Configuration

Features	Cortex-M0+ options	SAM L22 configuration
Interrupts	External interrupts 0-32	27
Data endianness	Little-endian or big-endian	Little-endian
SysTick timer	Present or absent	Present
Number of watchpoint comparators	0, 1, 2	2
Number of breakpoint comparators	0, 1, 2, 3, 4	4
Halting debug support	Present or absent	Present
Multiplier	Fast or small	Fast (single cycle)
Single-cycle I/O port	Present or absent	Present
Wake-up interrupt controller	Supported or not supported	Not supported
Vector Table Offset Register	Present or absent	Present
Unprivileged/Privileged support	Present or absent	Present
Memory Protection Unit	Not present or 8-region	8-region
Reset all registers	Present or absent	Absent
Instruction fetch width	16-bit only or mostly 32-bit	32-bit

The ARM Cortex-M0+ core has two bus interfaces:

- Single 32-bit AMBA-3 AHB-Lite system interface that provides connections to peripherals and all system memory, which includes flash and RAM.
- Single 32-bit I/O port bus interfacing to the PORT and DIVAS with 1-cycle loads and stores.

11.1.2. Cortex M0+ Peripherals

- System Control Space (SCS)
  - The processor provides debug through registers in the SCS. Refer to the Cortex-M0+ Technical Reference Manual for details (http://www.arm.com)
- Nested Vectored Interrupt Controller (NVIC)
  - External interrupt signals connect to the NVIC, and the NVIC prioritizes the interrupts. Software can set the priority of each interrupt. The NVIC and the Cortex-M0+ processor core are closely coupled, providing low latency interrupt processing and efficient processing of late

arriving interrupts. Refer to NVIC-Nested Vector Interrupt Controller and the Cortex-M0+ Technical Reference Manual for details (http://www.arm.com).

Note: When the CPU frequency is much higher than the APB frequency it is recommended to insert a memory read barrier after each CPU write to registers mapped on the APB. Failing to do so in such conditions may lead to unexpected behavior such as e.g. re-entering a peripheral interrupt handler just after leaving it.

- System Timer (SysTick)
  - The System Timer is a 24-bit timer clocked by CLK_CPU that extends the functionality of both the processor and the NVIC. Refer to the Cortex-M0+ Technical Reference Manual for details (http://www.arm.com).
- System Control Block (SCB)
  - The System Control Block provides system implementation information, and system control. This includes configuration, control, and reporting of the system exceptions. Refer to the Cortex-M0+ Devices Generic User Guide for details (http://www.arm.com).
- Micro Trace Buffer (MTB)
  - The CoreSight MTB-M0+ (MTB) provides a simple execution trace capability to the Cortex-M0+ processor. Refer to section MTB-Micro Trace Buffer and the CoreSight MTB-M0+ Technical Reference Manual for details (http://www.arm.com).
- Memory Protection Unit (MPU)
  - The Memory Protection Unit divides the memory map into a number of regions, and defines the location, size, access permissions and memory attributes of each region. Refer to the Cortex-M0+ Devices Generic User Guide for details (http://www.arm.com)

11.1.3. Cortex M0+ Address Map

Table 11-2. Cortex-M0+ Address Map

Address	Peripheral
0xE000E000	System Control Space (SCS)
0xE000E010	System Timer (SysTick)
0xE000E100	Nested Vectored Interrupt Controller (NVIC)
0xE000ED00	System Control Block (SCB)
0x41006000	Micro Trace Buffer (MTB)

Related Links

Product Mapping on page 30

11.1.4. I/O Interface

The device allows direct access to PORT registers. Accesses to the AMBA® AHB-Lite™ and the single cycle I/O interface can be made concurrently, so the Cortex M0+ processor can fetch the next instructions while accessing the I/Os. This enables single cycle I/O access to be sustained for as long as necessary.

11.2. Nested Vector Interrupt Controller

11.2.1. Overview

The Nested Vectored Interrupt Controller (NVIC) in the SAM L22 supports 32 interrupts with four different priority levels. For more details, refer to the Cortex-M0+ Technical Reference Manual (http://www.arm.com).

11.2.2. Interrupt Line Mapping

Each of the interrupt lines is connected to one peripheral instance, as shown in the table below. Each peripheral can have one or more interrupt flags, located in the peripheral's Interrupt Flag Status and Clear (INTFLAG) register.

An interrupt flag is set when the interrupt condition occurs. Each interrupt in the peripheral can be individually enabled by writing a '1' to the corresponding bit in the peripheral's Interrupt Enable Set (INTENSET) register, and disabled by writing '1' to the corresponding bit in the peripheral's Interrupt Enable Clear (INTENCLR) register.

An interrupt request is generated from the peripheral when the interrupt flag is set and the corresponding interrupt is enabled.

The interrupt requests for one peripheral are ORed together on system level, generating one interrupt request for each peripheral. An interrupt request will set the corresponding interrupt pending bit in the NVIC interrupt pending registers (SETPEND/CLRPEND bits in ISPR/ICPR).

For the NVIC to activate the interrupt, it must be enabled in the NVIC interrupt enable register (SETENA/CLRENA bits in ISER/ICER). The NVIC interrupt priority registers IPR0-IPR7 provide a priority field for each interrupt.

Table 11-3. Interrupt Line Mapping

Peripheral source	NVIC line
EIC NMI – External Interrupt Controller	NMI
PM – Power Manager MCLK - Main Clock OSCCTRL - Oscillators Controller OSC32KCTRL - 32KHz Oscillators Controller PAC - Peripheral Access Controller SUPC - Supply Controller	0
WDT – Watchdog Timer	1
RTC – Real Time Counter	2
EIC – External Interrupt Controller	3
FREQM - Frequency Meter	4
USB - Universal Serial Bus	5
NVMCTRL – Non-Volatile Memory Controller	6
DMAC - Direct Memory Access Controller	7

Peripheral source	NVIC line
EVSYS – Event System	8
SERCOM0 – Serial Communication Interface 0	9
SERCOM1 – Serial Communication Interface 1	10
SERCOM2 – Serial Communication Interface 2	11
SERCOM3 – Serial Communication Interface 3	12
SERCOM4 – Serial Communication Interface 4	13
SERCOM5 – Serial Communication Interface 5	14
TCC0 – Timer Counter for Control 0	15
TC0 – Timer Counter 0	16
TC1 – Timer Counter 1	17
TC2 – Timer Counter 2	18
TC3 – Timer Counter 3	19
ADC – Analog-to-Digital Converter	20
AC – Analog Comparator	21
PTC – Peripheral Touch Controller	22
SLCD - Segmented LCD Controller	23
AES - Advanced Encryption Standard module	24
TRNG - True Random Number Generator	25

11.3. Micro Trace Buffer

11.3.1. Features

- Program flow tracing for the Cortex-M0+ processor
- MTB SRAM can be used for both trace and general purpose storage by the processor
- The position and size of the trace buffer in SRAM is configurable by software
- CoreSight compliant

11.3.2. Overview

When enabled, the MTB records the changes in program flow that are reported by the Cortex-M0+ processor over the execution trace interface. This interface is shared between the Cortex-M0+ processor and the CoreSight MTB-M0+. The information is stored by the MTB in the SRAM as trace packets. An off-chip debugger can extract the trace information using the Debug Access Port to read the trace information from the SRAM. The debugger can then reconstruct the program flow from this information.

The MTB stores trace information into the SRAM and gives the processor access to the SRAM simultaneously. The MTB ensures that trace write accesses have priority over processor accesses.

An execution trace packet consists of a pair of 32-bit words that the MTB generates when it detects a non-sequential change of the program pounter (PC) value. A non-sequential PC change can occur during

branch instructions or during exception entry. See the CoreSight MTB-M0+ Technical Reference Manual for more details on the MTB execution trace packet format.

Tracing is enabled when the MASTER.EN bit in the Master Trace Control Register is 1. There are various ways to set the bit to 1 to start tracing, or to 0 to stop tracing. See the CoreSight Cortex-M0+ Technical Reference Manual for more details on the Trace start and stop and for a detailed description of the MTB's MASTER register. The MTB can be programmed to stop tracing automatically when the memory fills to a specified watermark level or to start or stop tracing by writing directly to the MASTER.EN bit. If the watermark mechanism is not being used and the trace buffer overflows, then the buffer wraps around overwriting previous trace packets.

The base address of the MTB registers is 0x41006000; this address is also written in the CoreSight ROM Table. The offset of each register from the base address is fixed and as defined by the CoreSight MTB-M0+ Technical Reference Manual. The MTB has four programmable registers to control the behavior of the trace features:

- POSITION: Contains the trace write pointer and the wrap bit
- MASTER: Contains the main trace enable bit and other trace control fields
- FLOW: Contains the WATERMARK address and the AUTOSTOP and AUTOHALT control bits
- BASE: Indicates where the SRAM is located in the processor memory map. This register is provided to enable auto discovery of the MTB SRAM location by a debug agent

See the CoreSight MTB-M0+ Technical Reference Manual for a detailed description of these registers.

11.4. High-Speed Bus System

11.4.1. Overview

11.4.2. Features

High-Speed Bus Matrix has the following features:

- Symmetric crossbar bus switch implementation
- Allows concurrent accesses from different masters to different slaves
- 32-bit data bus
- Operation at a one-to-one clock frequency with the bus masters

11.4.3. Configuration

Figure 11-1. Master-Slave Relations High-Speed Bus Matrix

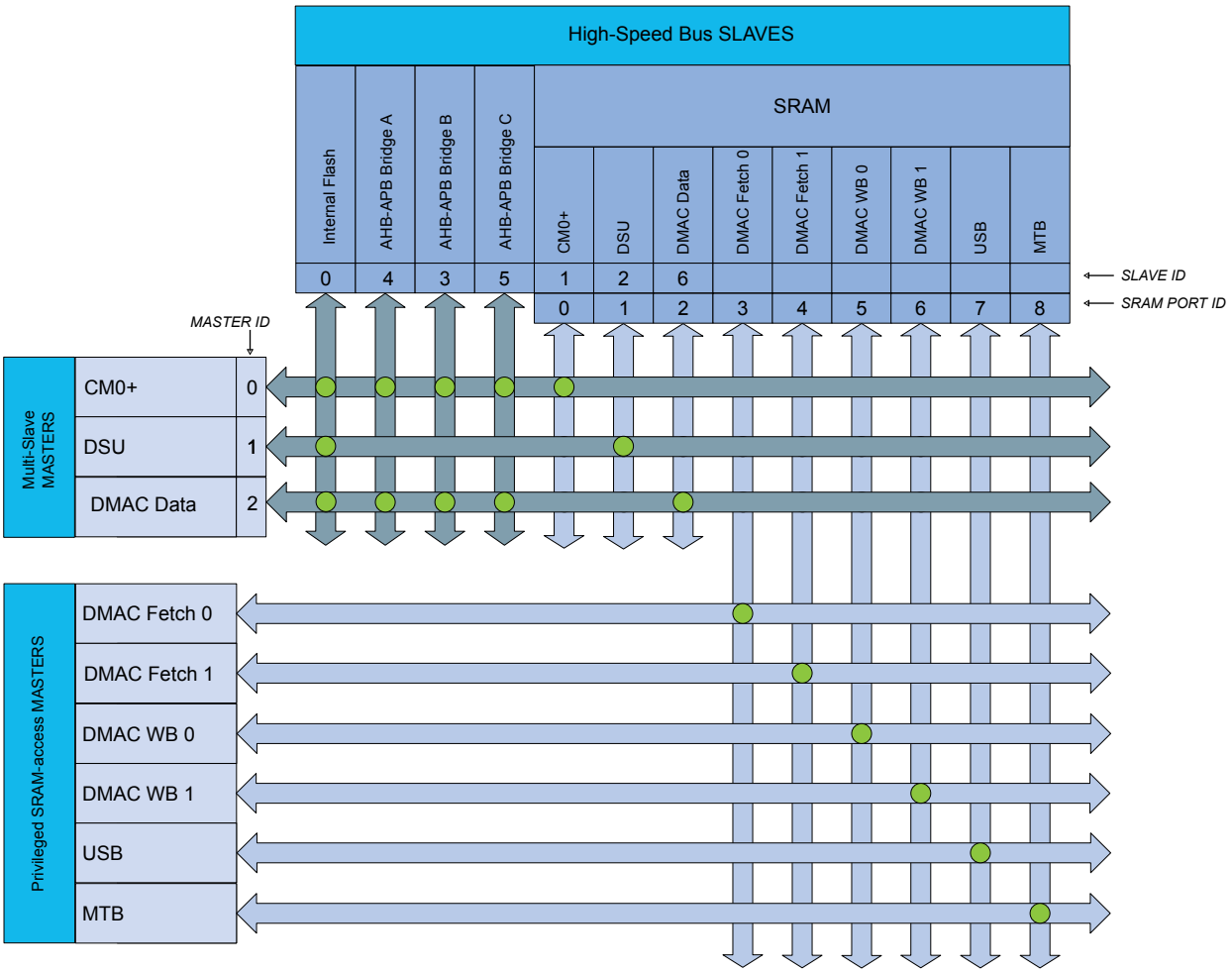


Table 11-4. High Speed Bus Matrix Masters

High-Speed Bus Matrix Masters	Master ID
CM0+ - Cortex M0+ Processor	0
DSU - Device Service Unit	1
DMAC - Direct Memory Access Controller / Data Access	2

Table 11-5. High-Speed Bus Matrix Slaves

High-Speed Bus Matrix Slaves	Slave ID
Internal Flash Memory	0
SRAM Port 0 - CM0+ Access	1
SRAM Port 1 - DSU Access	2
AHB-APB Bridge B	3
AHB-APB Bridge A	4

High-Speed Bus Matrix Slaves	Slave ID
AHB-APB Bridge C	5
SRAM Port 2 - DMAC Data Access	6

11.4.4. SRAM Quality of Service

To ensure that masters with latency requirements get sufficient priority when accessing RAM, priority levels can be assigned to the masters for different types of access.

The Quality of Service (QoS) level is independently selected for each master accessing the RAM. For any access to the RAM, the RAM also receives the QoS level. The QoS levels and their corresponding bit values for the QoS level configuration is shown in the table below.

Table 11-6. Quality of Service

Value	Name	Description
0x0	DISABLE	Background (no sensitive operation)
0x1	LOW	Sensitive Bandwidth
0x2	MEDIUM	Sensitive Latency
0x3	HIGH	Critical Latency

If a master is configured with QoS level DISABLE (0x0) or LOW (0x1) there will be a minimum latency of one cycle for the RAM access.

The priority order for concurrent accesses are decided by two factors. First, the QoS level for the master and second, a static priority given by the port ID. The lowest port ID has the highest static priority. See the tables below for details.

The MTB has a fixed QoS level HIGH (0x3).

The CPU QoS level can be written/read, using 32-bit access only, at address 0x4100C114, bits [1:0]. Its reset value is 0x3.

Refer to different master QOSCTRL registers for configuring QoS for the other masters (USB, DMAC).

Table 11-7. SRAM Port Connections QoS

SRAM Port Connection	Port ID	Connection Type	QoS	default QoS
CM0+ - Cortex M0+ Processor	0	Bus Matrix	0x4100C114, bits[1:0](1)	0x3
DSU - Device Service Unit	1	Bus Matrix	0x4100201C, bits[1:0](1)	0x2
DMAC - Direct Memory Access Controller - Data Access	2	Bus Matrix	IP-QOSCTRL.DQOS	0x2

SRAM Port Connection	Port ID	Connection Type	QoS	default QoS
DMAC - Direct Memory Access Controller - Fetch Access	3, 4	Direct	IP-QOSCTRL.FQOS	0x2
DMAC - Direct Memory Access Controller - Write-Back Access	5, 6	Direct	IP-QOSCTRL.WRBQOS	0x2
USB - Universal Serial Bus	7	Direct	IP-QOSCTRL	0x3
MTB - Micro Trace Buffer	8	Direct	STATIC-3	0x3

Note: 1. Using 32-bit access only.

12. Packaging Information

12.1. Thermal Considerations

12.1.1. Thermal Resistance Data

The following table summarizes the thermal resistance data depending on the package.

Table 12-1. Thermal Resistance Data

Package Type	θ_{JA}	θ_{JC}
48-pin TQFP	64.2°C/W	12.3°C/W
64-pin TQFP	60.8°C/W	12.0°C/W
100-pin TQFP	58.5°C/W	12.7°C/W
48-pin QFN	32.4°C/W	11.2°C/W
64-pin QFN	32.7°C/W	10.8°C/W
49-pin WLCSP	37.3°C/W	5.8°C/W

Related Links

Junction Temperature on page 42

12.1.2. Junction Temperature

The average chip-junction temperature, T_J, in °C can be obtained from the following:

1. $T_J = T_A + (P_D \times \theta_{JA})$
2. $T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$

where:

- θ_{JA} = Package thermal resistance, Junction-to-ambient (°C/W), see Thermal Resistance Data
- θ_{JC} = Package thermal resistance, Junction-to-case thermal resistance (°C/W), see Thermal Resistance Data
- $\theta_{HEATSINK}$ = Thermal resistance (°C/W) specification of the external cooling device
- P_D = Device power consumption (W)
- T_A = Ambient temperature (°C)

From the first equation, the user can derive the estimated lifetime of the chip and decide if a cooling device is necessary or not. If a cooling device is to be fitted on the chip, the second equation should be used to compute the resulting average chip-junction temperature T_J in °C.

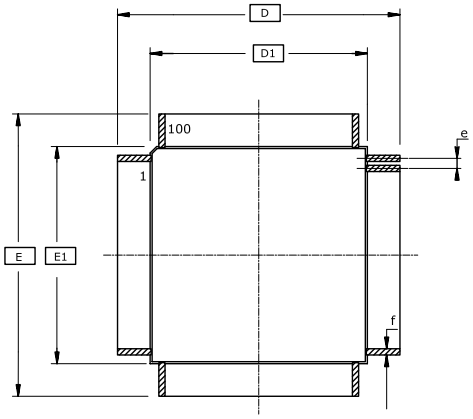
Related Links

Thermal Resistance Data on page 42

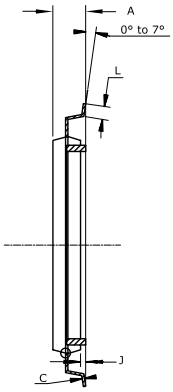
12.2. Package Drawings

12.2.1. 100 pin TQFP

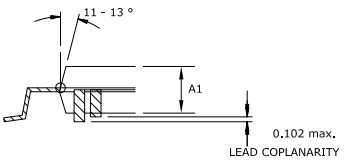
DRAWINGS NOT SCALED



TOP VIEW



SIDE VIEW



DETAIL VIEW

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.95	-----	1.05	
C	0.09	-----	0.20	
D/E		16.00		
D1/E1		14.00		2
J	0.05	-----	0.15	
L	0.45	-----	0.75	
e		0.50 BSC		
f	0.17	-----	0.27	
n		100		

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation AED.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

Table 12-2. Device and Package Maximum Weight

520	mg

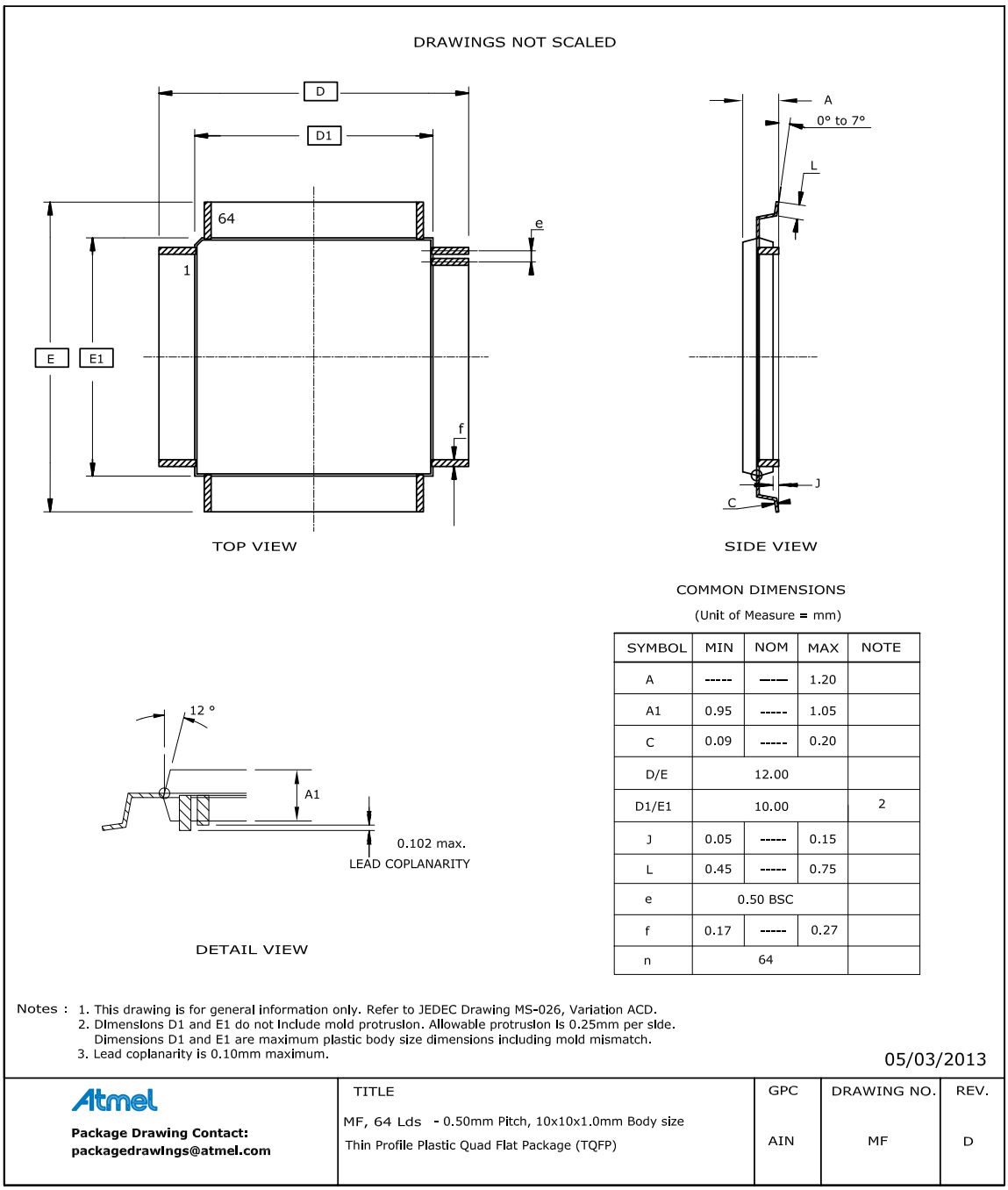
Table 12-3. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 12-4. Package Reference

JEDEC Drawing Reference	MS-026, variant AED
JESD97 Classification	e3

12.2.2. 64 pin TQFP



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.95	-----	1.05	
C	0.09	-----	0.20	
D/E		12.00		
D1/E1		10.00		2
J	0.05	-----	0.15	
L	0.45	-----	0.75	
e		0.50 BSC		
f	0.17	-----	0.27	
n		64		

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation ACD.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

05/03/2013

Atmel	TITLE	GPC	DRAWING NO.	REV.
Package Drawing Contact: packagedrawings@atmel.com	MF, 64 Lds - 0.50mm Pitch, 10x10x1.0mm Body size Thin Profile Plastic Quad Flat Package (TQFP)	AIN	MF	D

Table 12-5. Device and Package Maximum Weight

300	mg

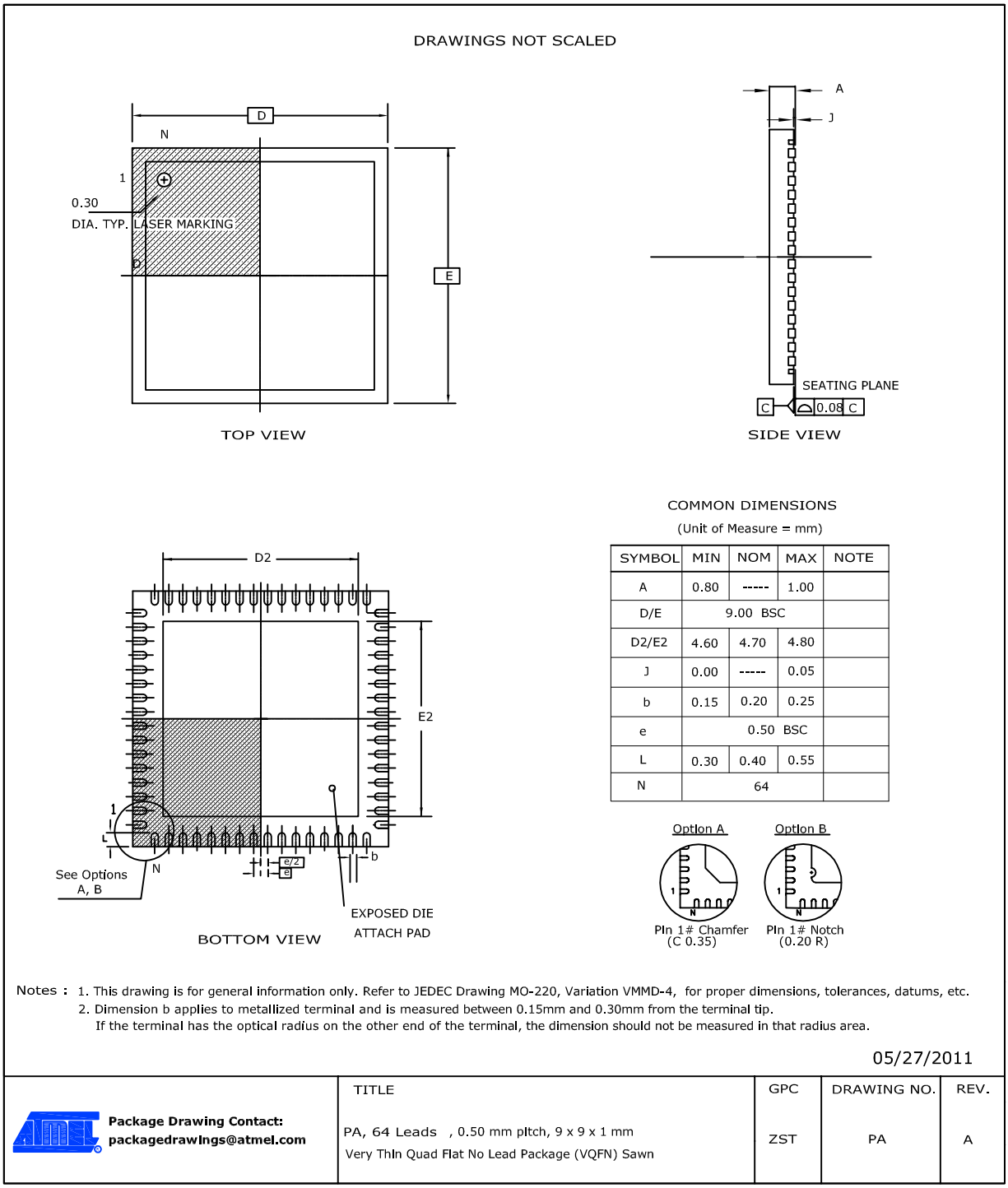
Table 12-6. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 12-7. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

12.2.3. 64 pin QFN



Note: The exposed die attach pad is not connected electrically inside the device.

Table 12-8. Device and Package Maximum Weight

200	mg

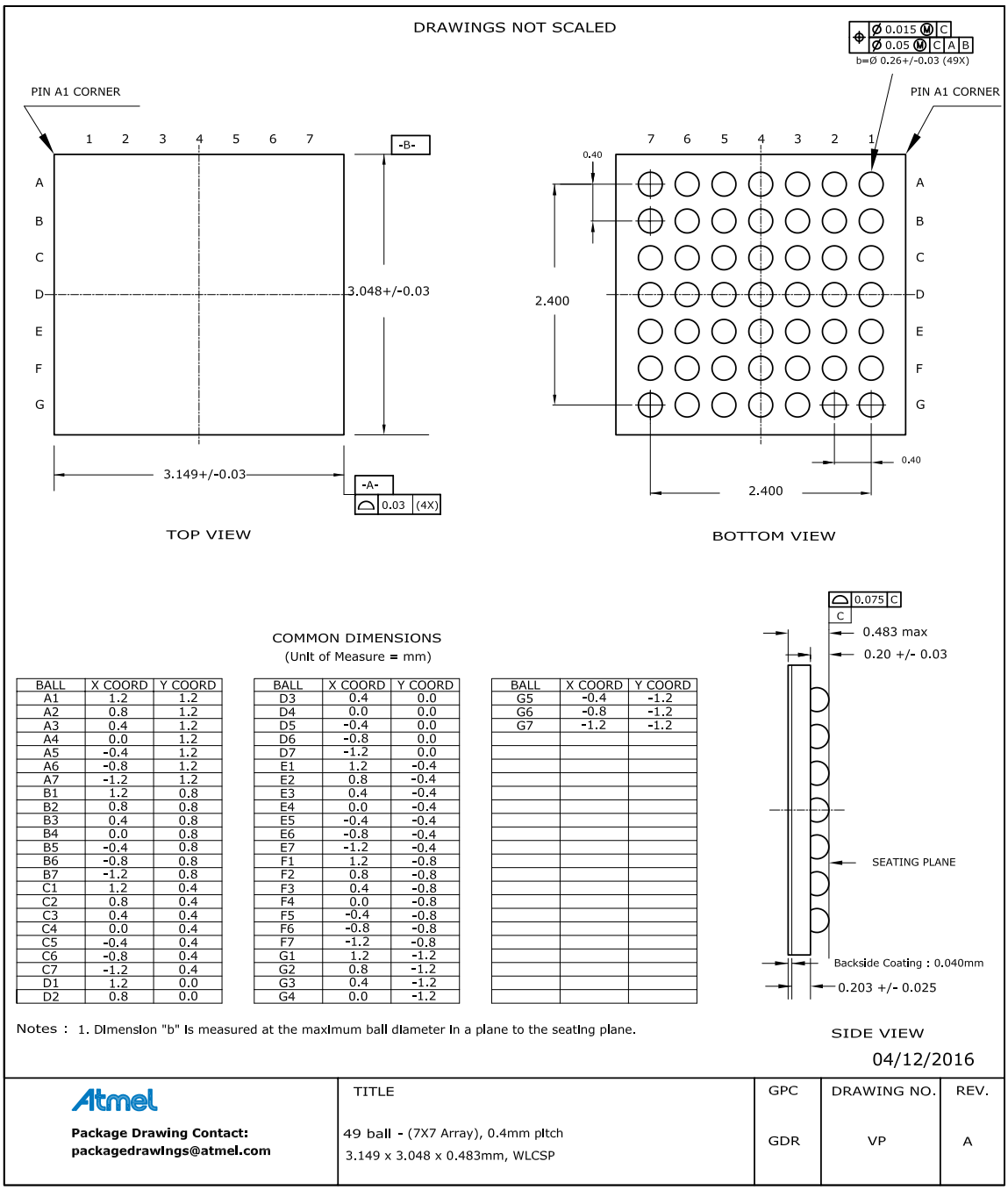
Table 12-9. Package Charateristics

Moisture Sensitivity Level	MSL3

Table 12-10. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

12.2.4. 49-Ball WLCSP



BALL	X COORD	Y COORD
A1	1.2	1.2
A2	0.8	1.2
A3	0.4	1.2
A4	0.0	1.2
A5	-0.4	1.2
A6	-0.8	1.2
A7	-1.2	1.2
B1	1.2	0.8
B2	0.8	0.8
B3	0.4	0.8
B4	0.0	0.8
B5	-0.4	0.8
B6	-0.8	0.8
B7	-1.2	0.8
C1	1.2	0.4
C2	0.8	0.4
C3	0.4	0.4
C4	0.0	0.4
C5	-0.4	0.4
C6	-0.8	0.4
C7	-1.2	0.4
D1	1.2	0.0
D2	0.8	0.0

BALL	X COORD	Y COORD
D3	0.4	0.0
D4	0.0	0.0
D5	-0.4	0.0
D6	-0.8	0.0
D7	-1.2	0.0
E1	1.2	-0.4
E2	0.8	-0.4
E3	0.4	-0.4
E4	0.0	-0.4
E5	-0.4	-0.4
E6	-0.8	-0.4
E7	-1.2	-0.4
F1	1.2	-0.8
F2	0.8	-0.8
F3	0.4	-0.8
F4	0.0	-0.8
F5	-0.4	-0.8
F6	-0.8	-0.8
F7	-1.2	-0.8
G1	1.2	-1.2
G2	0.8	-1.2
G3	0.4	-1.2
G4	0.0	-1.2

BALL	X COORD	Y COORD
G5	-0.4	-1.2
G6	-0.8	-1.2
G7	-1.2	-1.2

Table 12-11. Device and Package Maximum Weight

8.45	mg

Table 12-12. Package Characteristics

Moisture Sensitivity Level	MSL1

Table 12-13. Package Reference

JEDEC Drawing Reference	N/A
JESD97 Classification	E1

12.2.5. 48 pin TQFP

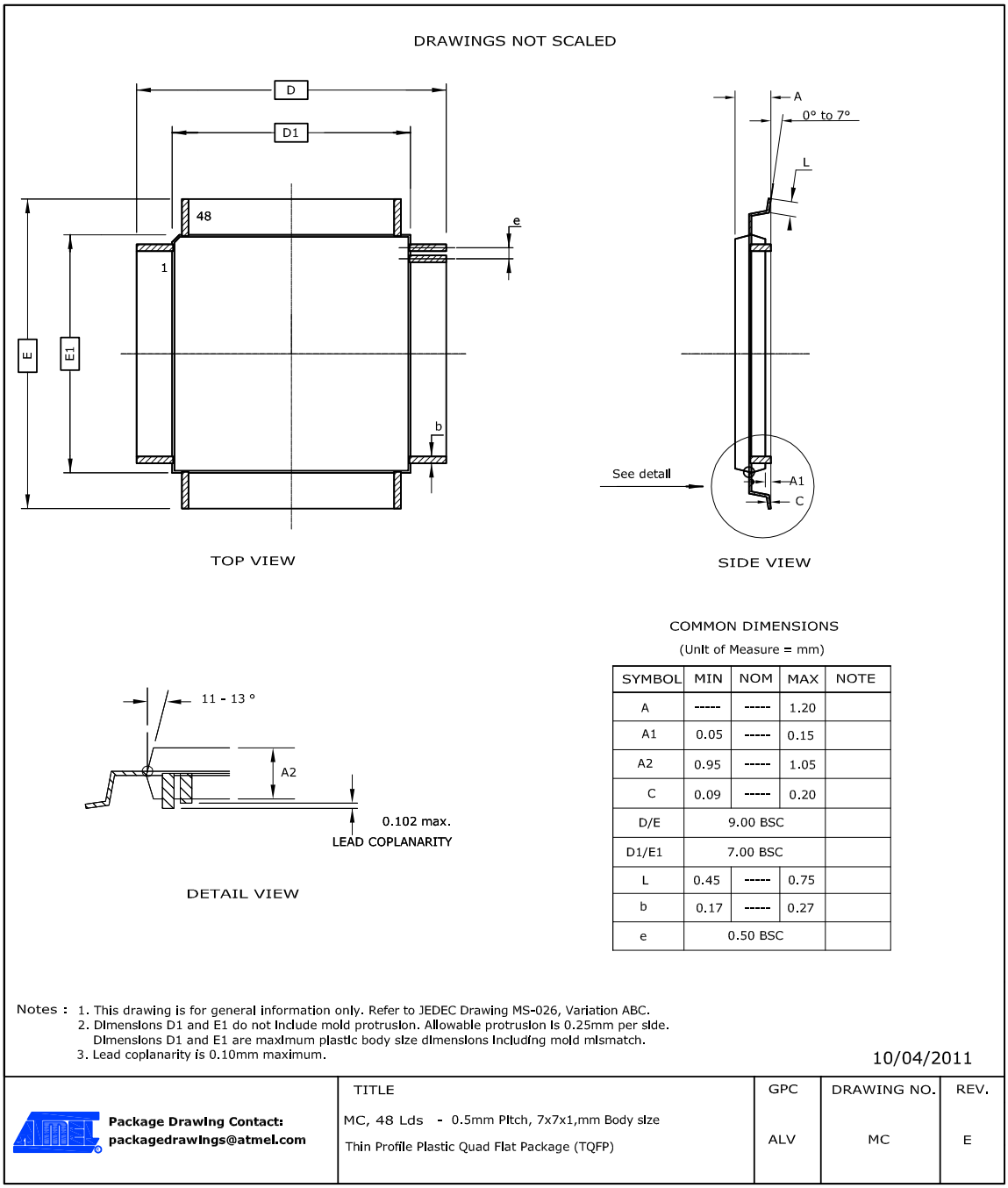


Table 12-14. Device and Package Maximum Weight

140	mg

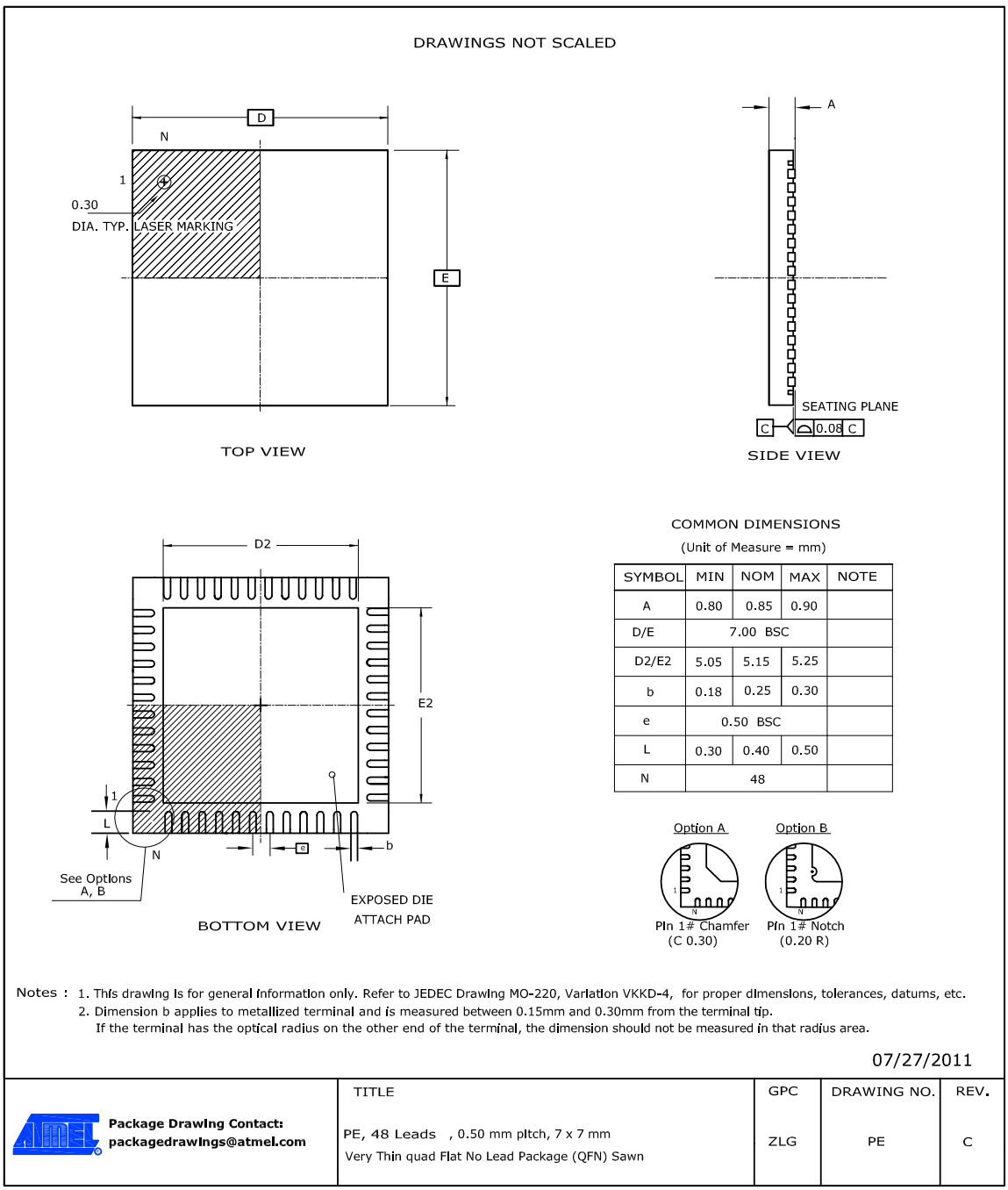
Table 12-15. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 12-16. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

12.2.6. 48 pin QFN



Note: The exposed die attach pad is not connected electrically inside the device.

Table 12-17. Device and Package Maximum Weight

140	mg

Table 12-18. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 12-19. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

12.3. Soldering Profile

The following table gives the recommended soldering profile from J-STD-20.

Table 12-20.

Profile Feature	Green Package
Average Ramp-up Rate (217°C to peak)	3°C/s max.
Preheat Temperature 175°C ±25°C	150-200°C
Time Maintained Above 217°C	60-150s
Time within 5°C of Actual Peak Temperature	30s
Peak Temperature Range	260°C
Ramp-down Rate	6°C/s max.
Time 25°C to Peak Temperature	8 minutes max.

A maximum of three reflow passes is allowed per component.

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